

IO-Link Common Profile

Specification

**Version 1.0
July 2017**

Order No: 10.072

File name: IOL_Common-Profile_V10_Jul2017.docx

Any comments, proposals, requests on this document are appreciated. Please use www.io-link-projects.com for your entries and provide name and email address.

Login: *IOL-SM-Profile*

Password: *Report*

Important notes:

NOTE 1 The IO-Link Community Rules shall be observed prior to the development and marketing of IO-Link products. The document can be downloaded from the www.io-link.com portal.

NOTE 2 Any IO-Link device shall provide an associated IODD file. Easy access to the file and potential updates shall be possible. It is the responsibility of the IO-Link device manufacturer to test the IODD file with the help of the IODD-Checker tool available per download from www.io-link.com.

NOTE 3 Any IO-Link devices shall provide an associated manufacturer declaration on the conformity of the device with this specification, its related IODD, and test documents, available per download from www.io-link.com.


Disclaimer:

The attention of adopters is directed to the possibility that compliance with or adoption of IO-Link Community specifications may require use of an invention covered by patent rights. The IO-Link Community shall not be responsible for identifying patents for which a license may be required by any IO-Link Community specification, or for conducting legal inquiries into the legal validity or scope of those patents that are brought to its attention. IO-Link Community specifications are prospective and advisory only. Prospective users are responsible for protecting themselves against liability for infringement of patents.

The information contained in this document is subject to change without notice. The material in this document details an IO-Link Community specification in accordance with the license and notices set forth on this page. This document does not represent a commitment to implement any portion of this specification in any company's products.

WHILE THE INFORMATION IN THIS PUBLICATION IS BELIEVED TO BE ACCURATE, THE IO-LINK COMMUNITY MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS MATERIAL INCLUDING, BUT NOT LIMITED TO ANY WARRANTY OF TITLE OR OWNERSHIP, IMPLIED WARRANTY OF MERCHANTABILITY OR WARRANTY OF FITNESS FOR PARTICULAR PURPOSE OR USE.

In no event shall the IO-Link Community be liable for errors contained herein or for indirect, incidental, special, consequential, reliance or cover damages, including loss of profits, revenue, data or use, incurred by any user or any third party. Compliance with this specification does not absolve manufacturers of IO-Link equipment, from the requirements of safety and regulatory agencies (TÜV, BIA, UL, CSA, etc.).

 **IO-Link** ® is registered trade mark. The use is restricted for members of the IO-Link Community. More detailed terms for the use can be found in the IO-Link Community Rules on www.io-link.com.

Conventions:

In this specification the following key words (in **bold** text) will be used:

may: indicates flexibility of choice with no implied preference.

should: indicates flexibility of choice with a strongly preferred implementation.

shall: indicates a mandatory requirement. Designers **shall** implement such mandatory requirements to ensure interoperability and to claim conformity with this specification.

Publisher:

IO-Link Community

Haid-und-Neu-Str. 7

76131 Karlsruhe

Germany

Phone: +49 721 / 96 58 590

Fax: +49 721 / 96 58 589

E-mail: info@io-link.com

Web site: www.io-link.com

© No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

CONTENTS

1	Scope	7
2	Normative references	7
3	Terms, definitions, symbols, abbreviated terms and conventions	7
3.1	Terms and definitions.....	7
3.2	Profile Guideline : Additional terms and definitions	9
3.3	Symbols and abbreviated terms	10
3.4	Conventions.....	11
3.4.1	Behavioral descriptions.....	11
3.4.2	Memory and transmission octet order	11
4	Objectives for Device profiles	12
4.1	Purpose of Device profiles	12
4.2	Interoperability.....	12
5	Device profiles related to IEC 61131-9	14
5.1	SDCI technology specified in IEC 61131-9.....	14
5.2	Profile classification	14
5.3	Concept of profiles.....	15
5.3.1	Basic requirements for profile Devices.....	15
5.3.2	Distinct profiles.....	15
5.3.3	Generic profiles	15
5.4	Profile characteristics	16
5.5	Concept of FunctionClasses	17
5.6	User benefits	19
6	Rules and constraints for developing Device profiles	19
6.1	How to create a Device profile	19
6.2	Basic parameter rules	20
6.3	Basic Process Data structure rules	21
6.4	Profile EventCodes	21
7	Identification and Diagnosis (I&D).....	21
7.1	Overview	21
7.2	Proxy Function Block for Identification and Diagnosis	22
Annex A (normative)	FunctionClasses	23
A.1	Overview	23
A.2	Device identification objects [0x8000]	23
A.3	Process Data mapping (PDV) [0x8002]	23
A.3.1	Overview	23
A.3.2	Profile specific PD structures.....	24
A.3.3	General rules for Process Data mapping.....	24
A.3.4	One or more BDCs (recommended)	24
A.3.5	One PDV	25
A.3.6	PD lengths up to two octets	25
A.3.7	One PDV and several BDCs	25
A.3.8	One PDV, several BDCs, and auxiliary variables	25
A.3.9	PD lengths larger than two octets	26

A.3.10	Process data description	27
A.4	Diagnosis [0x8003]	27
A.5	Extended Identification [0x8100]	27
Annex B (normative)	Profile relevant Device parameters	28
B.1	Overview	28
B.2	Mandatory SystemCommands	29
B.3	Identification parameters	29
B.4	ProfileCharacteristics parameter	29
B.5	Process data structure descriptors	30
B.5.1	Coding of PVinD and PVoutD	30
B.5.2	PD Input Descriptor	30
B.5.3	PD Output Descriptor	30
B.6	Extended Identification parameters	31
B.7	Diagnosis parameters	32
Annex C (normative)	Function block definitions	33
C.1	Overview	33
C.2	Proxy function block (FB) for identification and diagnosis	33
Annex D (normative)	IODD definition and rules	36
D.1	Overview	36
D.2	Constraints and rules	36
D.3	Name definitions	36
D.3.1	Profile type characteristic names	36
D.4	IODD Menu definitions	36
D.4.1	Overview	36
D.4.2	Menu structure of the ProfileIdentifier	36
Annex E (informative)	Device integration strategies into automation systems	38
E.1	Overview	38
E.1.1	Data and information providers and consumers	38
E.1.2	Consistency of data and information	39
E.1.3	Profile specific data types	40
E.1.4	Memory and transmission octet order	40
E.2	Integration via process image	40
E.2.1	General	40
E.2.2	Import of TAG lists based on the IODD	41
E.2.3	Decomposing packed process data values	42
E.3	Integration via PROXY function block (IEC 61131-3)	43
E.3.1	IEC 61131-3 programming languages	43
E.3.2	Function Blocks and Function Calls according IEC 61131-3	44
E.3.3	Concept of PROXY Function Blocks	45
E.3.4	Device profile activities	46
E.4	Integration into self-configuring systems	47
Annex F (informative)	Scaling and dimensions	48
F.1	Gradient and offset	48
F.2	Conversions	48
Annex G (normative)	Profile testing and conformity	49
G.1	General	49
G.1.1	Overview	49
G.1.2	Issues for additional testing/checking of profile Devices	49

Annex H (informative) Information on conformity testing of profile Devices	50
Bibliography.....	51
Figure 1 – Memory and transmission octet order.....	11
Figure 2 – Compatibility levels based on IEC 62390	12
Figure 3 – Domain of the SDCI technology within the automation hierarchy	14
Figure 4 – Overview of SDCI technologies and profiles	14
Figure 5 – Indication rules for ProfileIdentifiers	16
Figure 6 – Overview of typical FunctionClasses	17
Figure 7 – Typical object model for Device profiles	18
Figure A.1 – Example PDinput data stream.....	24
Figure A.2 – Recommended data structure for pure BDCs	24
Figure A.3 – Recommended data structure for one PDV	25
Figure A.4 – Recommended data structure for a PDV and up to two BDCs	25
Figure A.5 – Recommended data structure for a PDV, BDCs, and auxiliary variables.....	26
Figure A.6 – Recommended data structure for multiple PDVs and zero or more BDCs	26
Figure B.1 – Condensed transmission of StringT variables	32
Figure C.1 – Proxy FB for Device Identification and Diagnosis	33
Figure D.1 – Data flow within automation systems	37
Figure E.1 – Data flow within automation systems	38
Figure E.2 – Data types within automation systems	39
Figure E.3 – Use cases and data type recommendations	39
Figure E.4 – Transformation from SDCI to process image of boolean data	41
Figure E.5 – Transformation from SDCI to process image of complex data	41
Figure E.6 – Integration via process image	42
Figure E.7 – Relationship between a dimensioned PDV and its PLC variable	42
Figure E.8 – Example PLC program for a measurement value conversion	43
Figure E.9 – Function block and its instance data	45
Figure E.10 – PROXY FB using standardized SDCI communication FB.....	46
Figure E.11 – Standardized SDCI communication FB "IX_RD_WR"	46
Figure F.1 – Value to quantity conversion via linear equation.....	48
Figure F.2 – Conversion examples.....	48
Table 1 – Explanation of compatibility levels.....	13
Table 2 – Explanation of Device features	13
Table 3 – Coding of ProfileIdentifiers (PID)	16
Table 4 – Example of the profile identification of a distinct switching sensor	17
Table 5 – Example of the profile identification of a Generic Sensor.....	17
Table 6 – Tag notation for BDC and PDV access of a PLC client	19
Table 7 – Excerpt of the SDCI Indices related to profiles	20
Table 8 – Identification and Diagnosis Device profile	21
Table A.1 – Overview of FunctionClasses	23
Table B.1 – General profile relevant Device parameters	28
Table B.2 – Parameter "SystemCommand"	29
Table B.3 – Definitions for identification data objects	29
Table B.4 – Parameter "ProfileCharacteristics"	30
Table B.5 – Coding of PVinD or PVoutD	30
Table B.6 – Structure of "PD Input Descriptor"	30
Table B.7 – Structure of "PD Output Descriptor"	31
Table B.8 – Parameter Extended Identification	31
Table B.9 – Structure of "Detailed Device Status"	32
Table C.1 – Variables of "IOL_IdentificationAndDiagnosis" FB	33
Table C.2 – Elements of the IdentificationObjects	35
Table E.1 – PLC data types (IEC 61131-3)	40
Table E.2 – Characteristic of IEC 61131-3 programming languages	44

1 **0 Introduction**

2 **0.1 General**

3 The Single-drop Digital Communication Interface (SDCI) and system technology (IO-Link™¹)
4 for low-cost sensors and actuators is standardized within IEC 61131-9 [2]. The technology is
5 an answer to the need of these digital/analog sensors and actuators to exchange process data,
6 diagnosis information and parameters with a controller (PC or PLC) using a low-cost, digital
7 communication technology while maintaining backward compatibility with the current DI/DO sig-
8 nals as defined in IEC 61131-2.

9 Any SDCI compliant Device can be attached to any available interface port of an SDCI Master.
10 SDCI compliant Devices perform physical to digital conversion in the Device, and then com-
11 municate the result directly in a standard 24 V I/O digital format, thus removing the need for
12 different DI, DO, AI, AO modules and a variety of cables.

13 Physical topology is point-to-point from each Device to the Master using 3 wires over distances
14 up to 20 m. The SDCI physical interface is backward compatible with the usual 24 V I/O signal-
15 ling specified in IEC 61131-2. Transmission rates of 4,8 kbit/s, 38,4 kbit/s and 230,4 kbit/s are
16 supported.

17 Tools allow the association of Devices with their corresponding electronic I/O device descrip-
18 tions (IODD) and their subsequent configuration to match the application requirements [3].

19 This document describes the common parts of sensor and actuator models to be used in all
20 Device profiles.

21 This document follows the IEC 62390 [4] to a certain extent.

22 Terms of general use are defined in IEC 61131-1 or in [5]. Specific SDCI terms are defined in
23 this part.

24 **0.2 Patent declaration**

25 There are no known patents related to the content of this document.

26 Attention is drawn to the possibility that some of the elements of this document may be the
27 subject of patent rights. The IO-Link Community shall not be held responsible for identifying
28 any or all such patent rights.

29

¹ IO-Link™ is a trade name of the "IO-Link Community". This information is given for the convenience of users of this specification. Compliance to this specification does not require use of the registered logos for IO-Link™. Use of the registered logos for IO-Link™ requires permission of the "IO-Link Community".

Common Profile — Related to IEC 61131-9

30
31
32

33 **1 Scope**

34 The single-drop digital communication interface (SDCI) technology described in part 9 of the
35 IEC 61131 series focuses on simple sensors and actuators in factory automation, which are
36 nowadays using small and cost-effective microcontrollers. With the help of the SDCI technology,
37 the existing limitations of traditional signal connection technologies such as switching 0/24 V,
38 analog 0 to 10 V, etc. can be turned into a smooth migration. Classic sensors and actuators are
39 usually connected to a fieldbus system via input/output modules in so-called remote I/O periph-
40 erals. The (SDCI) Master function enables these peripherals to map SDCI Devices onto a
41 fieldbus system or build up direct gateways. Thus, parameter data can be transferred from the
42 PLC level down to the sensor/actuator level and diagnosis data transferred back in turn by
43 means of the SDCI communication. This is a contribution to consistent parameter storage and
44 maintenance support within a distributed automation system. SDCI is compatible to classic sig-
45 nal switching technology according to part 2 of the IEC 61131 series.

46 This document defines the common characteristics (models) of Device profiles. These models
47 comprise process data structures, identification objects, best practice handling of quantity
48 measurements with or without associated units, and diagnosis objects.

49 This document contains statements on conformity testing for all Device profiles.

50 **2 Normative references**

51 The following referenced documents are indispensable for the application of this document. For
52 dated references, only the edition cited applies. For undated references, the latest edition of
53 the referenced document (including any amendments) applies.

54 IEC 61131-3, *Programmable controllers – Part 3: Programming languages*

55 IEC 61131-9, *Programmable controllers – Part 9: Single-drop digital communication interface
56 for small sensors and actuators (SDCI)*

57 **3 Terms, definitions, symbols, abbreviated terms and conventions**

58 **3.1 Terms and definitions**

59 For the purposes of this document, the following terms and definitions in addition to those given
60 in IEC 61131-1 and IEC 61131-2 apply.

61 **3.1.1**

62 **ApplicationSpecificTag**

63 read/write data object for the user application to identify the specific Device

64 [SOURCE: IEC 61131-9, B.2.16]

65 **3.1.2**

66 **Device**

67 single passive peer to a Master such as a sensor or actuator

68 Note 1 to entry: Uppercase "Device" is used for SDCI equipment, while lowercase "device" is used in a generic
69 manner.

70 [SOURCE: IEC 61131-9, 3.1.14]

71 **3.1.3**

72 **DeviceID**

73 unique Device identification allocated by a vendor

74 [SOURCE: IEC 61131-9, B.1.9]

- 75 **3.1.4**
76 **Event**
77 instance of a change of conditions in a Device
- 78 Note 1 to entry: Uppercase "Event" is used for SDCI Events, while lowercase "event" is used in a generic manner.
79 Note 2 to entry: An Event is indicated via the Event flag within the Device's status cyclic information; then acyclic
80 transfer of Event data (typically diagnosis information) is conveyed through the diagnosis communication channel.
81 [SOURCE: IEC 61131-9, 3.1.17]
- 82 **3.1.5**
83 **FirmwareRevision**
84 vendor specific coding of the firmware revision of the Device
- 85 [SOURCE: IEC 61131-9, B.2.15]
- 86 **3.1.6**
87 **HardwareRevision**
88 vendor specific coding for the hardware revision of the Device
- 89 [SOURCE: IEC 61131-9, B.2.14]
- 90 **3.1.7**
91 **Master**
92 active peer connected through ports to one up to n Devices and which provides an interface to
93 the gateway to the upper level communication systems or PLCs
- 94 Note 1 to entry: Uppercase "Master" is used for SDCI equipment, while lowercase "master" is used in a generic
95 manner.
96 [SOURCE: IEC 61131-9, 3.1.27]
- 97 **3.1.8**
98 **port**
99 communication medium interface of the Master to one Device
- 100 [SOURCE: IEC 61131-9, 3.1.31]
- 101 **3.1.9**
102 **Process Data**
103 PD
104 input or output values from or to a discrete or continuous automation process cyclically trans-
105 ferred with high priority and in a configured schedule automatically after start-up of a Master
- 106 [SOURCE: IEC 61131-9, 3.1.33]
- 107 **3.1.10**
108 **ProductID**
109 vendor specific product or type identification
- 110 [SOURCE: IEC 61131-9, B.2.11]
- 111 **3.1.11**
112 **ProductName**
113 product name to distinguish between variants
- 114 [SOURCE: IEC 61131-9, B.2.10]
- 115 **3.1.12**
116 **ProductText**
117 additional product information such as product category
- 118 [SOURCE: IEC 61131-9, B.2.12]

- 119 **3.1.13**
120 **SerialNumber**
121 unique vendor specific code for each individual Device
122 [SOURCE: IEC 61131-9, B.2.13]
- 123 **3.1.14**
124 **switching signal**
125 binary signal from or to a Device when in SIO mode (as opposed to the "coded switching" SDCI
126 communication)
127 [SOURCE: IEC 61131-9, 3.1.38]
- 128 **3.1.15**
129 **VendorID**
130 unique vendor identification assigned by the IO-Link community
131 [SOURCE: IEC 61131-9, B.1.8]
- 132 **3.1.16**
133 **VendorName**
134 vendor name associated to the VendorID
135 [SOURCE: IEC 61131-9, B.2.8]
- 136 **3.1.17**
137 **VendorText**
138 additional information about the vendor
139 [SOURCE: IEC 61131-9, B.2.9]
- 140 **3.2 Profile Guideline : Additional terms and definitions**
- 141 **3.2.1**
142 **BinaryDataChannel**
143 BDC
144 binary information as switching or control signal
- 145 **3.2.2**
146 **data (digital)**
147 quantities, characters, or symbols on which operations are performed by a processor within an
148 automation device, transmitted in the form of electrical signals, stored and recorded on mag-
149 netic, optical, or mechanical recording media, and displayed on human machine interfaces
- 150 EXAMPLE A number '32' and the characters '°C' represent digital data, whereas the combination '32 °C' represents
151 information
- 152 Note 1 to entry: Digital data, information, and knowledge describe an ascending seamless concept correlated to
153 syntax, semantics, and reasoning
- 154 **3.2.3**
155 **Function block**
156 software functional element comprising an individual, named copy of a data structure and as-
157 sociated operations specified by a corresponding function block type
- 158 [SOURCE: IEC 62390, 3.1.13]
- 159 **3.2.4**
160 **FunctionClass**
161 particular function within a Device profile
- 162 Note 1 to entry: A profile Device can use one or several FunctionClasses once or several times.

163 **3.2.5**
164 **information**
165 any propagation of cause and effect within an automation system conveyed either as the con-
166 tent of a message or through direct or indirect observation

167 EXAMPLE Correlated data presented on a display

168 Note 1 to entry: Digital data, information, and knowledge describe an ascending seamless concept correlated to
169 syntax, semantics, and reasoning

170 **3.2.6**
171 **knowledge**
172 understanding of real things such as causes and effects (processes) as well as abstract con-
173 cepts

174 EXAMPLE Longer-term interpretation of information

175 Note 1 to entry: Knowledge can be acquired by a cognitive observer of information

176 Note 2 to entry: Digital data, information, and knowledge describe an ascending seamless concept correlated to
177 syntax, semantics, and reasoning

178 **3.2.7**
179 **ProcessDataVariable**
180 PDV
181 Representation of process values

182 **3.2.8**
183 **ProfileIdentifier**
184 unique identifier for Device Profile, CommonApplicationProfile, or FunctionClass

185 **3.2.9**
186 **Process Variable Input Descriptor**
187 PVinD
188 descriptor for position and offset of variables within the Process (input) Data entity

189 **3.2.10**
190 **Process Variable Output Descriptor**
191 PVoutD
192 descriptor for position and offset of variables within the Process (output) Data entity

193 **3.3 Symbols and abbreviated terms**

DI	Digital input
DO	Digital output
I/O	Input / output
OD	On-request Data
PD	Process Data
PLC	Programmable logic controller
SDCI	Single-drop digital communication interface
SIO	Standard Input Output (binary switching signal)

[IEC 61131-2]

194

195 **3.4 Conventions**

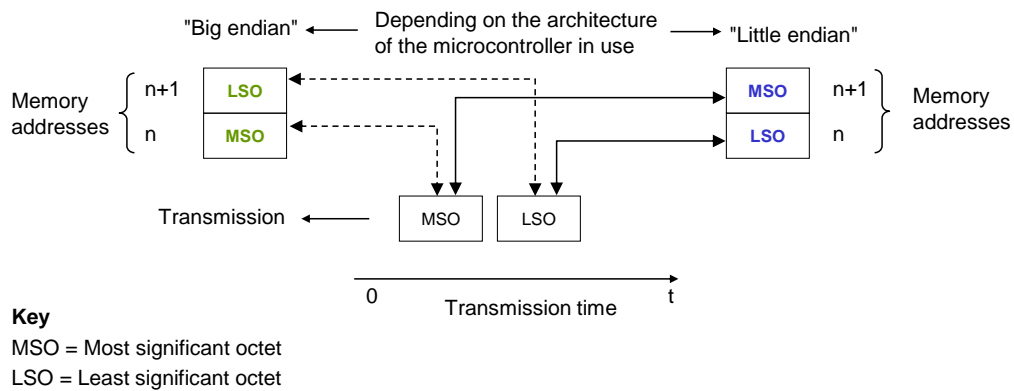
196 **3.4.1 Behavioral descriptions**

197 For the behavioral descriptions, the notations of UML2 [12] are used, mainly state diagrams.
 198 The layout of the associated state-transition tables is following IEC 62390 [4].

199 The state diagrams shown in this document are entirely abstract descriptions. They do not
 200 represent a complete specification for implementation.

201 **3.4.2 Memory and transmission octet order**

202 Figure 1 demonstrates the order that shall be used when transferring WORD based data types
 203 from memory to transmission and vice versa (see also clause 7.3.3.2 in [1]).



204

205

Figure 1 – Memory and transmission octet order

206

207 4 Objectives for Device profiles

208 4.1 Purpose of Device profiles

209 In factory automation, sensors nowadays are using a broad spectrum of transducers based on
 210 many different physical or chemical effects. They are converting one or more physical or chem-
 211 ical quantities (for example position, pressure, temperature, substance, etc.) and propagate
 212 them in an appropriate form to data processing units such as for example PLCs.

213 Also actuators like lamps, locks, valves, motors, and so on are not only actuators. The internal
 214 states are going to be important for the customers. Even the acknowledged control and config-
 215 uration is of increasing importance and not covered by simple digital output signals.

216 It is the purpose of SDCI to overcome the limitations of the classic Device interfaces DI, DO,
 217 AI, and AO via a point-to-point digital communication that allows transmitting digitally not only
 218 binary and/or analog information but additional information also. Very often, the changes to the
 219 core sensor or actuator application ("sensor/actuator technology") are very little during the mi-
 220 gration to SDCI. However, the user realizes a dramatic increase in comfort and flexibility
 221 through the identification, parameterization, and diagnosis features.

222 As a consequence of the digitization, the Devices can also provide many more technology fea-
 223 tures and data structures to the user for processing within for example a PLC user program
 224 than before with the classic interfaces.

225 Device profiles define terminologies, features, behaviours, commands, responses, correspond-
 226 ing data structures, and other things common to particular Device families and thus prevent the
 227 user from a confusing variety.

228 4.2 Interoperability

229 The major parts of the Device profiles deal with process data structures and behavior as well
 230 as parameter data structures and dynamic parameterization at runtime. These features stream-
 231 line the functions of comparable Devices though requiring more sophisticated and powerful PLC
 232 user programs. Thus, interoperability between existing user programs and Devices of a corre-
 233 sponding family is the goal of profile Device design and testing (see [4]). Figure 2 shows com-
 234 patibility levels based on IEC 62390.

Compatibility levels

Device features	Incom- patible	Coexistent	Interconnectable	Interfunctional	Interworkable	Interoperable	Interchangeable
Mechanics							X
Dynamic behavior						(X)	(X)
Application functionality						X	X
Parameter semantics					X	X	X
Data structures				X	X	X	X
Data types				X	X	X	X
Data access			X	X	X	X	X
Communication interface			X	X	X	X	X
Communication protocol		X	X	X	X	X	X

} Device profiles
} SDCI communication

235

236

Figure 2 – Compatibility levels based on IEC 62390

237 The different compatibility levels are described in Table 1 and the different Device features are
 238 described in Table 2, based on [4].

239

Table 1 – Explanation of compatibility levels

Compatibility level	Definition
Incompatible	Two or more devices are incompatible if they cannot exist together in the same distributed system
Coexistent	Two or more devices coexist on the same communications network if they can operate independently of one another in a physical communication network or can operate together using some or all of the same communication protocols, without interfering with the application of other devices on the network
Interconnectable	Two or more devices are interconnectable if they are using the same communication protocols, communication interface and data access
Interfunctional	Two or more devices are interfunctional if they can exchange data for specific purposes without manual configuration, the parameter semantics are defined and the devices provide the necessary identifier
Interworkable	Two or more devices are interworkable if they can transfer parameters between them, i.e. in addition to the communication protocol, communication interface and data access, the parameter data types are the same
Interoperable	Two or more devices are interoperable if they can work together to perform a specific role in one or more distributed applications. The parameters and their application related functionality fit together both syntactically and semantically. Interoperability is achieved when the devices support complementary sets of parameters and functions belonging to the same profile
Interchangeable	Unlike the other compatibility levels (which refer to two or more devices working in the same system) interchangeability refers to the replacement of one device with another. Devices are interchangeable for a given role in a distributed application if the new device has the functionality to meet the application requirements

240

241

Table 2 – Explanation of Device features

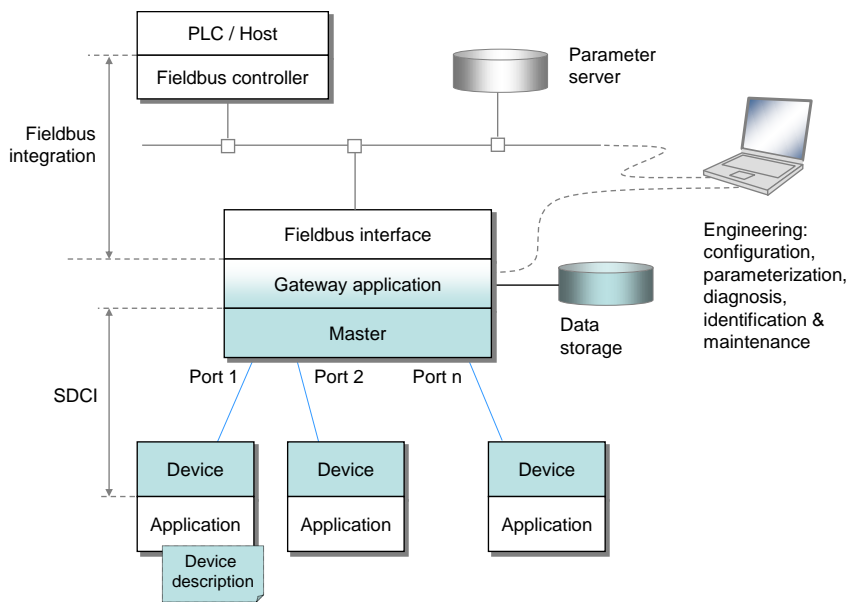
Device features	Definition
Mechanics	This feature is defined by the mechanical outline, process connector, and/or electrical connection
Dynamic behavior	This feature is defined by time constraints that influence the parameter update or the general device behavior. For example, the update rate of a process value can influence block algorithms.
Application functionality	This feature is defined by specifying the dependencies and consistency rules within the functional element. This is done in the parameter description characteristics or in the device behavior section
Parameter semantics	This feature is defined by the parameter characteristics: parameter name, parameter description, parameter range, substitute value of the parameter, default value, persistence of the parameter after power loss and deployment
Data structures	This feature is defined by the combination of data types, such as records of simple data types
Data types	This feature is defined by characteristics such as “data type”, see Note
Data access	This feature is defined by characteristics such “parameter timing” and “access direction”, see Note
Communication interface	This feature is defined by the protocols of layer 5 to 7 of the OSI reference model including the services and the service parameters. Additional mapping mechanisms can be necessary. The dynamic performance of the communication system is part of this feature
Communication protocol	This feature is defined by all protocols of layer 1 to 4 of the OSI reference model, i.e. from the physical medium access to the transport layer protocol

Device features	Definition
<p>Note:</p> <p>“parameter timing”: in the context of SDCI this refers to the used data channels like acyclic or process data</p> <p>“access direction”: specification whether the parameter can be read and/or written</p> <p>“data type”: IEC 61131-3 data types are preferred</p>	

242 **5 Device profiles related to IEC 61131-9**

243 **5.1 SDCI technology specified in IEC 61131-9**

244 Figure 3 shows the domain of the SDCI technology within the automation hierarchy.



245

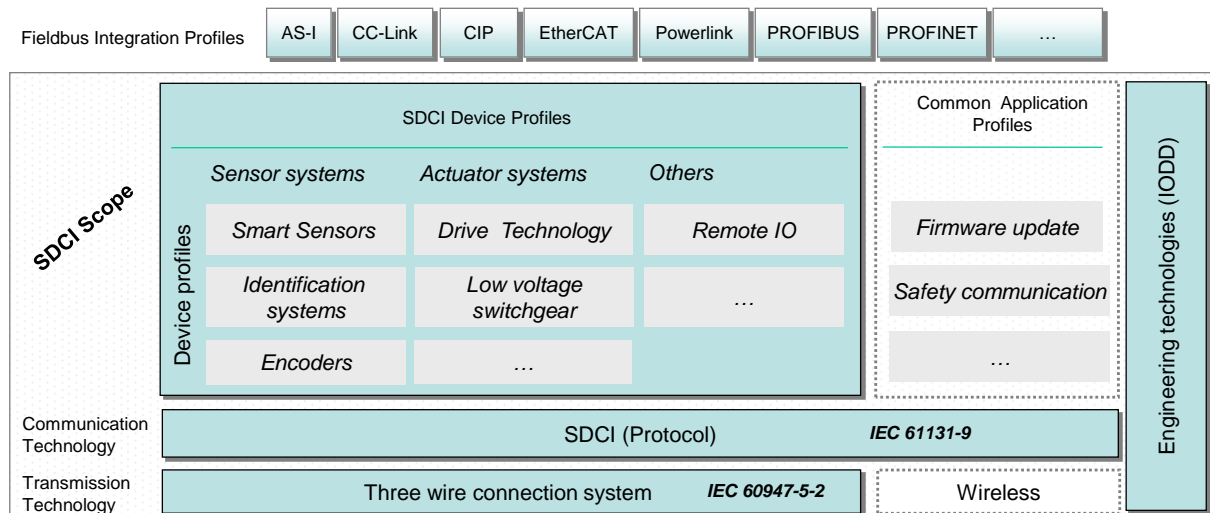
246

Figure 3 – Domain of the SDCI technology within the automation hierarchy

247 The SDCI technology defines a point-to-point digital communication interface for connecting
 248 "digital" or "analog" type sensors and actuators to a Master unit, which can be combined with
 249 gateway capabilities to become a fieldbus remote I/O node. The technology is specified in [1]
 250 and [3].

251 **5.2 Profile classification**

252 Figure 4 shows an overview of the SDCI technologies and profiles.



253

254

Figure 4 – Overview of SDCI technologies and profiles

255 The "SDCI Device Profiles" represent specifications of common functionality of particular De-
256 vice type families/classes such as

- 257 • smart sensors,
- 258 • identification systems,
- 259 • drives,
- 260 • low voltage switch gears,
- 261 • encoders,
- 262 • etc.

263 These profiles primarily focus on the structure and behavior of the Device technology and sec-
264 ondarily on the data structure mapping on SDCI. Thus, the user recognizes a "generic" Device
265 to a certain extent even when he switches from one brand to another.

266 The "Common Application Profiles" represent specifications that several Device type families/
267 classes can use. Examples are firmware update, functional safety communication or energy
268 management.

269 The "Fieldbus Integration Profiles" specify the adaptation of the SDCI technology to particular
270 fieldbuses. These specifications are outside the responsibility of the organization listed in An-
271 nex H. However, this organization is interested in harmonizing the "views" of SDCI users
272 through the different fieldbuses.

273 **5.3 Concept of profiles**

274 There are two approaches for profiling SDCI Devices. The distinct profile is strictly defined with
275 detailed process data layout and functionality. The generic profile uses different Function-
276 Classes to form a manufacturer specific Device behavior.

277 **5.3.1 Basic requirements for profile Devices**

278 As [1] defines only a few parameter as mandatory, the profile Devices shall support more pa-
279 rameters to allow standardized handling of these devices.

280 The following base features shall be supported by all profile devices :

- 281 • IO-Link Version 1.1
- 282 • ISDU support
- 283 • DataStorage for all remanent parameters
- 284 • Support of block parameter handling

285

286 **5.3.2 Distinct profiles**

287 The distinct profiles consist of a defined combination of one or multiple FunctionClasses iden-
288 tified by ProfileIdentifier. The mandatory FunctionClasses are defined in the related specifica-
289 tions and may contain FunctionClasses from different specifications. The Device functionality
290 may be extended by manufacturer specific parameters or additional FunctionClasses. The user
291 can always and only rely on the functions defined by the ProfileIdentifier of the Device, this
292 provides a higher level of interchangeability even between different manufacturers.

293 It can be compared with a tool box with dedicated and identical tools, the minimum set of tools
294 is defined, there may be more tools inside.

295 **5.3.3 Generic profiles**

296 The generic profiles consist of a manufacturer specific combination of different FunctionClasses
297 which may have variable definitions like process data layouts. The user can only rely on the
298 common subset of the referenced FunctionClasses, the interchangeability is reduced.

299 It can be compared with a tool box, the tools are nearly the same, but in every tool box is
300 another set of tools.

301 **5.4 Profile characteristics**

302 The profiles are based on the definition of FunctionClasses. These FunctionClasses can be
303 used as a standalone property or combined to ProfileIdentifier such as

- 304 • DeviceProfileIDs for particular classes of Devices, or
- 305 • CommonApplicationProfileIDs for generic use in all Devices.

306 The supported functionality of a Device shall be listed within an array of ProfileIdentifier. It is
307 also possible for a Device to support several DeviceProfiles, CommonApplicationProfiles as
308 well as additional FunctionClasses (see 5.5).

309 The DeviceProfiles or CommonApplicationProfiles define the mandatory FunctionClasses for
310 the specific ProfileIdentifier.

311 FunctionClasses defined in particular Device profiles can be inherited to other Device profiles.

312 Some FunctionClasses are highly recommended or mandatory for DeviceProfiles or Common-
313 ApplicationProfiles such as Device Identification or Device Diagnosis, see 6 or the specification
314 of the distinct profiles.

315 An overview of the defined ProfileIdentifier is available on www.io-link.com.

316 The parameter object "Profile Characteristic" supports up to 32 ID entries. Each and every
317 supported profile and FunctionClass shall be indicated and coded as specified in Table 3.
318 To avoid multiple occurrences of a ProfileIdentifier in the list, all FunctionClasses which are
319 included in the referenced ProfileIDs shall be omitted.

320 **Table 3 – Coding of ProfileIdentifiers (PID)**

Parameter object name	Data type	Value range	Profile type
ProfileIdentifier (PID)	UIntegerT16	0x0000 0x0001 to 0x3FFF 0x4000 to 0x7FFF 0x8000 to 0xBFFF 0xC000 to 0xFFFF	No profile supported DeviceProfileID CommonApplicationProfileID FunctionClassID Reserved

321

322 The following rules apply:

- 1) Whenever 1 to n Device profiles are supported, they shall be indicated via 1 to n DeviceProfileID entries
- 2) Whenever 1 to n common application profiles are supported, they shall be indicated via 1 to n CommonApplicationProfileIDs
- 3) Additionally supported FunctionClasses which are not covered by DeviceProfileIDs or CommonApplicationProfileIDs shall be indicated by 1 to n FunctionClassIDs
- 4) The IDs shall be listed in ascending order: DeviceProfileIDs → CommonApplicationProfileIDs → FunctionClassIDs

323

324

Figure 5 – Indication rules for ProfileIdentifiers

325 The different profile identifiers shall be ordered within the array of the parameter object "Profile
326 Characteristic" in a sequence shown in Table 4.

327

328 Table 4 shows the example content of the "Profile Characteristic" of an adjustable switching sensor.
 329

330 **Table 4 – Example of the profile identification of a distinct switching sensor**

Index	ProfileIdentifier type	Referenced Profile ID
0x000D	DeviceProfileID	0x0004: SSP 2.2
		0x4000: I&D

331
 332 Table 5 shows the example content of the "Profile Characteristic" of a Smart Sensor with addi-
 333 tional FunctionalClasses.

334 **Table 5 – Example of the profile identification of a Generic Sensor**

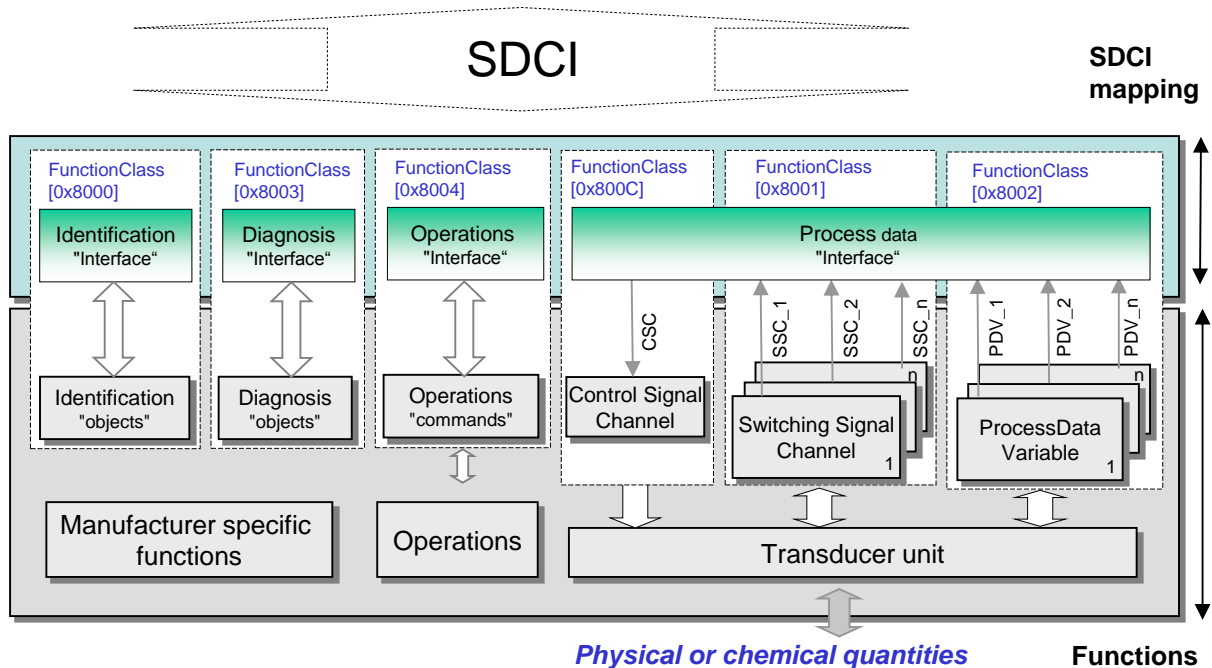
Index	ProfileIdentifier type	Referenced ProfileID
0x000D	DeviceProfileID	0x0001: Smart Sensor Profile
	FunctionClassID	0x8001: Binary Data Channel
		0x8002: Process Data Variable
		0x8004: Teach-in

335 For further details, see B.4.

336 **5.5 Concept of FunctionClasses**

337 So far only a so-called function-driven Device model instead of for example an architectural
 338 model is defined. That means it only defines independent and consistent functions (Function-
 339 Classes) that are available via the communication channels. This allows the community and the
 340 Device manufacturers/vendors to create a variety of subsets from basic switching sensors/ac-
 341 tuators using only the FunctionClasses like the Switching Signal Channel (SSC) up to complex
 342 sensors/actuators with several measurement values using the FunctionClasses like the Pro-
 343 cessDataVariables (PDV).

344 Figure 6 shows a structure of the function-driven Device model and its FunctionClasses.



345
 346 **Figure 6 – Overview of typical FunctionClasses**

347 A profile Device shall only support the indicated FunctionClasses. Normally, the measurement
348 technology (transducer) is manufacturer/vendor specific and not part of profiles.

349 Each and every FunctionClass consists of a communication dependent function and an associ-
350 ated mapping on the SDCI communication. FunctionClasses are represented and referenced
351 by ProfileIdentifiers, for example FunctionClassID = 0x8000, as shown in Figure 6.

352 The FunctionClasses DeviceIdentification, DeviceDiagnosis, ProcessDataVariable, and Ex-
353 tendedIdentification are highly recommended for all profile Devices. They are combined to the
354 DeviceProfile [0x4000] in this document. They may be defined as mandatory by definition of
355 any CommonApplicationProfile or DeviceProfile.

356 A Switching Signal Channel (e.g. FunctionClass [0x8001]) uses the measurement values out of
357 the transducer unit and creates switching information (SSCn), whenever certain thresholds are
358 passed. These thresholds are defined via parameters.

359 In case of an actuator, the FunctionClass [0x800C] is used for switching the transducer ON or
360 OFF.

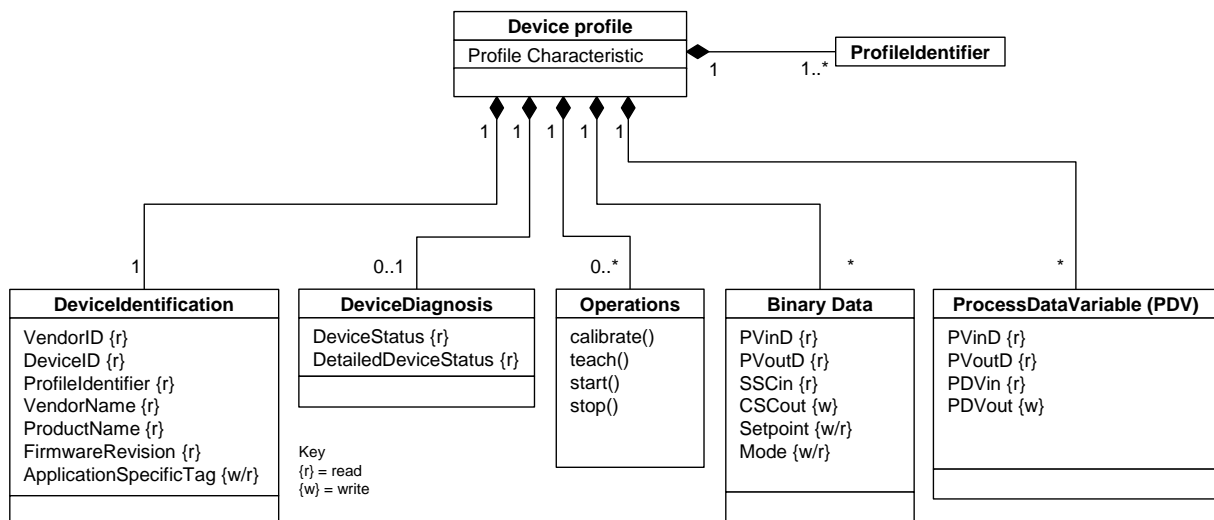
361 The ProcessDataVariables (FunctionClass [0x8002]) uses in case of a sensor the measurement
362 values out of the transducer unit and creates data structures (PDV_n) representing the physical
363 or chemical quantity, for example pressure or temperature. In case of an actuator, the values
364 are used to control the process. These data structures within the ProcessDataVariables are
365 standardized to a maximum extent as shown in A.3.

366 The operation commands like FunctionClasses [0x8007] to [0x8009] allow the user for example
367 to remotely adjust a Device in the automation process via the user program in a controller
368 (PLC).

369 The mapping of SSCs, CSCs and PDVs into SDCI communication messages is specified in the
370 corresponding FunctionClass definitions or at least in A.3. These data structures are designed
371 for simplicity and highest efficiency.

372 The shown combination is just an example and may be expanded by additional FunctionClasses
373 or reduced by omitting some of the FunctionClasses.

374 Figure 7 shows a possible object model of a combined sensor/actuator Device profile.



375

376

Figure 7 – Typical object model for Device profiles

377 The parameter "Profile Characteristic" contains at least one ProfileIdentifier or an array of Pro-
378 fileIdentifier. Besides the objects for identification and diagnosis, it contains the objects Pro-
379 cessDataVariable (PDV) and Binary Data Channel (SSC and CSC). These objects show the
380 associated attributes, whereas the object "Operations" shows only its defined methods (com-
381 mands).

382 The objects SSC, CSC and PDV can be used once or more times depending on the complexity
383 of the sensor/actuator.

384 The parameter set of a FunctionClass can be classified into two groups:

- 385 • Operating parameters, which can be modified during production, and
- 386 • Configuration parameters (static data), which are only set/modified during commissioning.

387

388 5.6 User benefits

389 As already mentioned in 5.2 the user recognizes from the Masters point of view a "generic"
390 Device through the communication interface even though he switches from one brand to an-
391 other. The customer experiences the following advantages of profile Devices at different points
392 in time:

- 393 • At commissioning time the process data can be easily configured due to reduced sets of
394 process data structures. In future this could be extended by explicit support of profile De-
395 vices by the system provider.
- 396 • At programming time the process data and common parameters can be used with expected
397 behavior and without checking the IODD of the specific Device just based on the profile
398 defined behavior. This will be supported by specific Proxy Function Blocks for the defined
399 Profiles.
- 400 • At runtime the Devices represent their process data in an equal manner and can be replaced
401 by Devices with the same ProfileIdentifier and the same physical measurement or actuator
402 behavior. For the replacement only the configured Device Identification has to be updated.

403 However, due to the objectives for the individual Device profiles, the interoperability levels can
404 be different and the compatibility between the profile Devices can be partly limited. For example
405 the measurement range of a sensor or actuator strength may be different and not suitable for
406 the specific application. It is the responsibility of system maintenance to check this prior to a
407 replacement of the Device.

408 A user program ("client") for example in a PLC can access the objects via corresponding func-
409 tions or methods respectively. Table 6 shows an example.

410 **Table 6 – Tag notation for BDC and PDV access of a PLC client**

Read/Write access	Description
Read Sensor1.AppSpecTag	Readout of the parameter "ApplicationSpecificTag" of the Device
Read Sensor1.DeviceStatus	Readout of the parameter "DeviceStatus"
Write Sensor1.switch point1.SetPointValueSP1	Write parameter "SetPointValueSP1"
Write Sensor1.TeachTP1	Start teach procedure for TP1

411

412 6 Rules and constraints for developing Device profiles

413 Within this clause the general rules and constraints for the design of future profile specification
414 are defined.

415 6.1 How to create a Device profile

416 When defining new Profiles or FunctionClasses, the following rules shall be observed

- 417 • Each profile defines the mandatory FunctionClasses within the specific ProfileIdentifier
- 418 • The FunctionClass Identification [0x8000] shall be mandatory for every ProfileIdentifier
- 419 • The FunctionClasses Diagnosis [0x8003] is highly recommended for every ProfileIdentifier
- 420 • There shall not be two or more FunctionClasses with an identical function (no duplicates)

- 421 • There will be no versioning of profiles (identifiers). Changes to a profile result in a new
422 ProfileIdentifier
- 423 • The profiles shall specify as mandatory all parameters and contents required to guarantee
424 the compatibility of profile Devices supporting a ProfileIdentifier
- 425 • The defined ProfileIdentifier and parameters shall be published in the SDCI Profile overview
426 as defined in 5.4
- 427 • Restrictions on combinations of ProfileIdentifier shall be described in the DeviceProfile or
428 FunctionClass definition (responsibility of the profile working group)
- 429 • FunctionClass specific parameters shall be defined with all attributes such as
430 – Parameter name as defined in the IODD
431 – Index
432 – Subindex access availability
433 – Subindex structure
434 – Subindex offset
435 – Parameter type or length
436 – Allowed parameter content
437 – Default value
438 – Access rights
439 – Mandatory, optional, or conditional availability
- 440 • FunctionClass specific process data structures shall be defined with all attributes such as
441 – Subindex structure
442 – Subindex offset
443 – Allowed process data content
444 – Validity rules
- 445 • Profile parameters shall use the index range reserved for the profile considering possibly
446 combinable profiles
- 447 • Profiles shall define their common EventCodes within range reserved for the profile consid-
448 ering possibly combinable Profiles

449 6.2 Basic parameter rules

450 The parameters defined in a Device profile shall be accessible as defined in the corresponding
451 ProfileIdentifier definition. In general, the rules of [1] apply. In detail the following rules shall be
452 observed

- 453 • Any parameter shall follow the accessibility rule defined in the profile
- 454 • Optional or conditional Subindices shall always be readable and return the defined default
455 value
- 456 • Optional or conditional Subindices with write access shall always accept a writing of the
457 defined default value

458 Table 7 shows the profile related Indices defined in [1]. It is the responsibility of the community
459 to avoid interferences and duplicates of parameters over different profile specifications.

460 **Table 7 – Excerpt of the SDCI Indices related to profiles**

Index (dec)	Object name	Access	Length	Data type	M/O/C	Smart Sensor profile definitions
...						
0x0031 to 0x003F (49 to 63)	Reserved for profiles					To be defined in profiles
...						
0x4000 to 0x4FFF (16384 to 20479)	Profile specific Index					To be defined in profiles
Key M = mandatory; O = optional; C = conditional						

461

462 **6.3 Basic Process Data structure rules**

463 For the layout of Process Data structures the following rules shall be observed

- 464 • BDCs are right-aligned in ascending order, always at bit offset 0 (Figure A.4 or Figure A.5)
- 465 PVinD in this case is: Set of BoolT.2.0
- 466 • PDV with e.g. UIntegerT12 is left-aligned mapped to bit offset 4 (Figure A.4 or Figure A.5)
- 467 PVinD in this case is: UIntegerT.12.4
- 468 • Auxiliary variables (e.g. qualifier information) shall be right-aligned to the BDCs
- 469 PVinD in this case is: UIntegerT.2.2 (Figure A.5)
- 470 • All variables starting at bit offset 16 shall be mapped octet aligned. Potential waste of bits
- 471 is accepted. Variables shall be casted to SDCI data structures if necessary. See Annex
- 472 E.2.3 and E.2.4 in [1] for casting rules.

473 In addition, it is highly recommended to observe the following rules

- 474 • Best practice for PDVs is the usage of UInteger16 or Integer16 respectively (easier data
- 475 processing)
- 476 • IntegerT to be favored over UIntegerT
- 477 • Manufacturer/vendor specific process data can use their own rules. However, it is highly
- 478 recommended to observe the rules within this profile

479 **6.4 Profile EventCodes**

480 Annex D in [1] and [2] reserves the EventCode range from 0xB000 to 0xBFFF for profiles.

481 If any profile defines EventCodes, also the trigger and behaviour accompanied to this event
482 shall be defined.483 **7 Identification and Diagnosis (I&D)**484 **7.1 Overview**485 It is very important to provide all necessary identification and diagnosis information in a unique
486 manner and with the same contents to interpret.487 As [1] specifies the required objects as optional, this CommonApplicationProfile specifies these
488 parameters as mandatory for the profile Devices489 Table 8 provides an overview of the FunctionClasses for Identification and Diagnosis. Since
490 there are no options only the ProfileIdentifier shall be listed in the ProfileCharacteristic Index,
491 see 5.4.

492

Table 8 – Identification and Diagnosis Device profile

ProfileID	Profile characteristic name	Function Classes		
0x4000	Identification and Diagnosis	0x8000	DeviceIdentification	See A.2
		0x8003	DeviceDiagnosis	See A.4
		0x8002	Pro- cessDataMapping	See A.3
		0x8100	ExtendedIdentifica- tion	See A.5

493

494 7.2 Proxy Function Block for Identification and Diagnosis

495 To ease the integration in Run-Time systems like PLCs, an appropriate FunctionCall is specified
496 in C.1. The FunctionBlock reads or writes identification or diagnosis data from the Device and
497 shows the status of the Function Block. The information is provided in a way an operator can
498 use directly in his PLC program for further handling. All specific action is taken without any
499 required specific knowledge of the operator.

Annex A (normative)

FunctionClasses

A.1 Overview

Table A.1 provides an overview of the defined FunctionClasses within this document.

Table A.1 – Overview of FunctionClasses

FunctionClass	Name	Reference / Clause
[0x8000]	DeviceIdentification	A.2
[0x8002]	ProcessDataVariable (PDV)	A.3
[0x8003]	DeviceDiagnosis	A.4
[0x8100]	ExtendedIdentification	A.5

A.2 Device identification objects [0x8000]

The FunctionClass 0x8000 defines some optional parameters as mandatory for profile Devices. These are

- Product ID
- Firmware Revision
- Application Specific Tag

The Product ID and the Firmware revision are unchanged to the definition in clause B.2.11 and B.2.15 of [1]. The parameter Application Specific Tag defined in clause B.2.16 in [1], is defined in this FunctionClass with the maximum size of 32 octets to get a maximum reusability over all profile Devices.

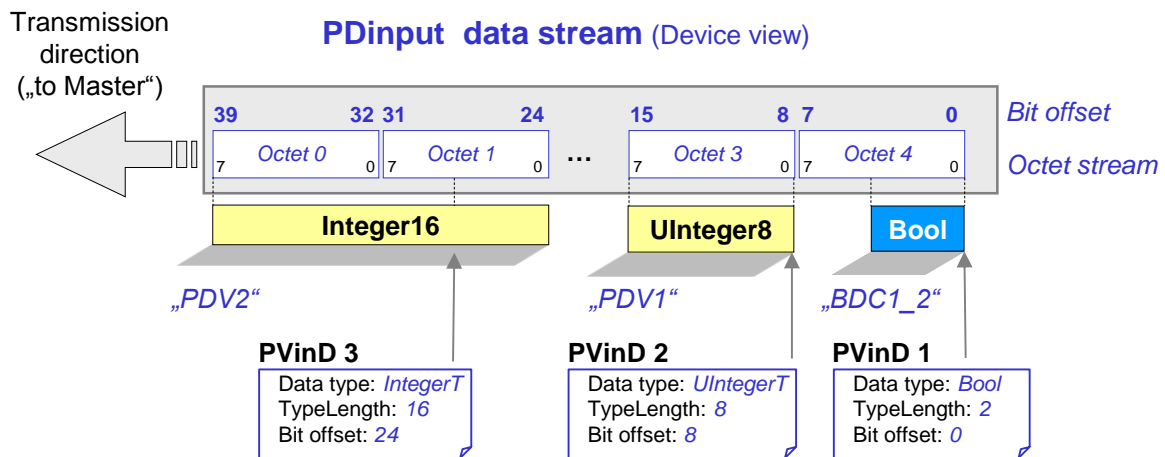
This standardized FunctionClass [0x8000] is mandatory for all Device profiles.

A.3 Process Data mapping (PDV) [0x8002]

A.3.1 Overview

Depending on the particular profile type, a Device arranges binary information (BDC) and/or ProcessDataVariables (PDV) for the cyclic transmission to and/or from the Master via SDCI in a so-called "PDinput data stream" and/or "PDoutput data stream".

Device profiles shall either define the data structures in a new FunctionClass or reference to this generic FunctionClass.



527

528

Figure A.1 – Example PDinput data stream

529 The "PDinput data stream" example shown in Figure A.1 comprises 5 octets (octet 0, 1, 2, 3, 4)
 530 to be transmitted to the Master. The profile technology (application) maps BDCs and PDVs into
 531 the data stream. The location of each of these data elements within the data stream is described
 532 in a process variable descriptor (PViND, PVoutD). Basis for this description is the "Bit offset"
 533 reaching from the last transmitted bit to the first one as defined in Annex E "Data types" in [1].

534 NOTE From the user program perspective, usage of standard data types such as UInteger16, or Integer16 would
 535 be the preferred way of mapping. However, due to performance reasons "packed" data structures cannot be avoided.

536 A.3.2 Profile specific PD structures

537 In order to avoid a large variety of data structures and descriptors and as a consequence com-
 538 plexity, this profile specification specifies and recommends only a few variable descriptions.

539 A.3.3 General rules for Process Data mapping

540 It is highly recommended to observe the following rules in order to simplify the programming
 541 and to increase performance:

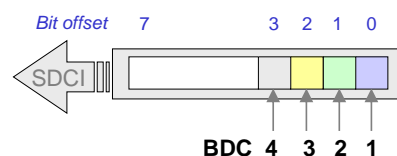
- 542 • PDVs of size > 15 bit should be represented in octet granular data types (16, 32, 64), pref-
 543 erably IntegerT
- 544 • For data < 16 bit the data type IntegerT should be used that is easily extendable to octet
 545 granular data types
- 546 • Preferred data lengths are 8, 12, 14, 16, 32, or 64 bit
- 547 • PDVs should carry dimensioned measurement values as shown in Figure F.2 and Figure E.

548

549 A.3.4 One or more BDCs (recommended)

550 It is highly recommended for pure binary profile Devices without additional PDVs to use the
 551 data structure demonstrated in Figure A.2. The number of supported BDCs, four in Figure A.2,
 552 defines the size of the bit field. The BDCs are right-aligned in ascending order without gaps.

553 The PViND in this case is: Set of BoolT.4.0



554

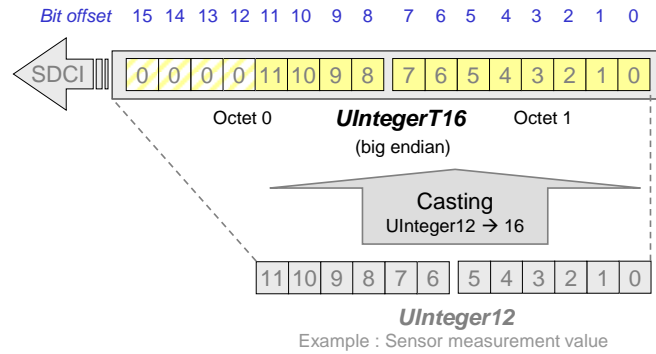
555

Figure A.2 – Recommended data structure for pure BDCs

556 **A.3.5 One PDV**

557 It is highly recommended for profile Devices with one PDV to use the data structure demon-
 558 strated in Figure A.3. The example shows, that a profile Device can cast an 8, 10, or 14 bit
 559 value into a UIntegerT16 data type, thereby using only part of the space. In this case the pad-
 560 ding bits shall be "0". Variables of type Integer < 16 bit shall also be casted into variables of
 561 type IntegerT16. Type casting rules are specified in Annex E.2.3 and E.2.4 in [1].

562 The PVinD in this case is: UIntegerT.16.0



563

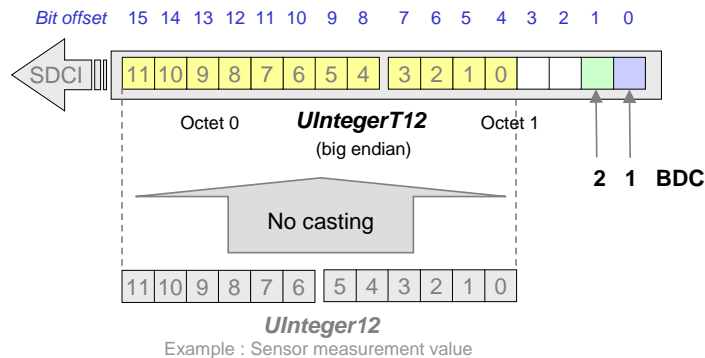
564 **Figure A.3 – Recommended data structure for one PDV**

565 **A.3.6 PD lengths up to two octets**

566 Exceptions exist for PD lengths up to two octets. Especially for bit offsets up to 16 other than
 567 octet aligned data types may be used ("packed format"). For PD with more than two octets the
 568 rules in A.3.9 apply.

569 **A.3.7 One PDV and several BDCs**

570 It is highly recommended for profile Devices with one PDV and one to two BDCs to use the data
 571 structure demonstrated in Figure A.4.



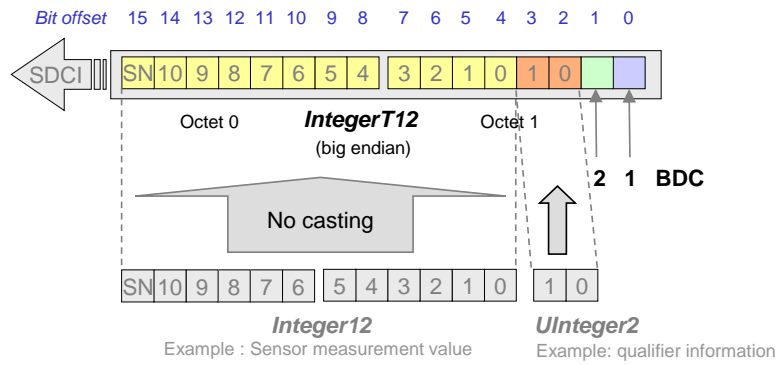
572

573 **Figure A.4 – Recommended data structure for a PDV and up to two BDCs**

574 The rules in 6.3 shall be observed.

575 **A.3.8 One PDV, several BDCs, and auxiliary variables**

576 It is highly recommended for Smart Sensors with one PDV, one to two BDCs, and auxiliary
 577 variables such as qualifiers to use the data structure demonstrated in Figure A.5.



578

579 **Figure A.5 – Recommended data structure for a PDV, BDCs, and auxiliary variables**

580 The rules in 6.3 shall be observed.

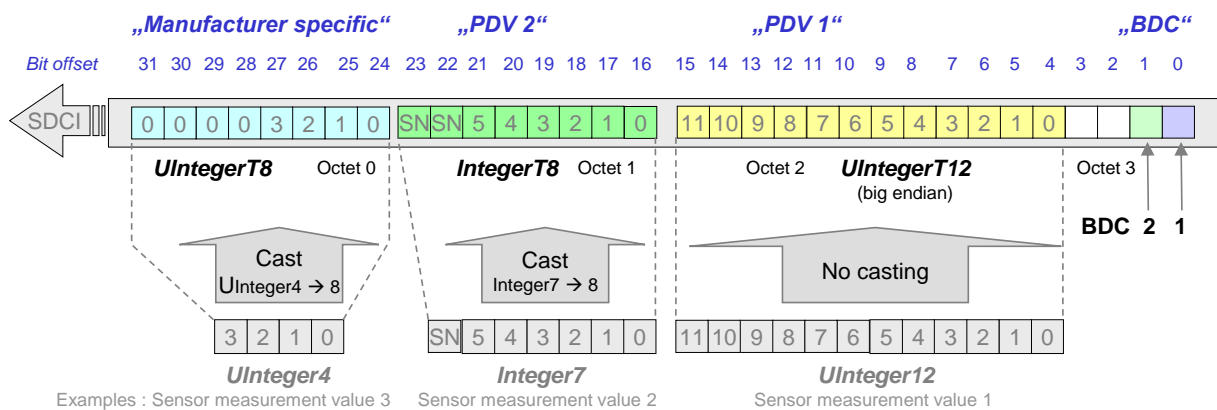
581 **A.3.9 PD lengths larger than two octets**

582 It is highly recommended for profile Devices with 0 or more BDCs, 2 or more PDVs, and manu-
 583 facturer/vendor specific process data (outside the scope of these profile definitions) to use the
 584 data structure demonstrated in the example in Figure A.6. The following rules shall be observed
 585 (mandatory):

- 586 • Within the first two octets the rules of A.3.6 apply. Especially the BDCs are always starting
 587 at bit offset 0.
- 588 • All variables starting at bit offset 16 shall be mapped octet aligned. Potential waste of bits
 589 is accepted. Variables shall be casted to SDCI data structures if necessary. See clauses
 590 Annex E2.3 and E2.4 in [1], for casting rules.

591 In addition, it is highly recommended to observe the following rules (recommended):

- 592 • Best practice for PDVs is the usage of UInteger16 or Integer16 respectively (easier data
 593 processing)
- 594 • IntegerT to be favored over UIntegerT
- 595 • Manufacturer/vendor specific process data can use their own rules. However, it is highly
 596 recommended to observe the rules within this profile



597

598 **Figure A.6 – Recommended data structure for multiple PDVs and zero or more BDCs**

599 The PViNDs in Figure A.6 are:

- | | | |
|-------------|------------------|--------------------------------|
| 600 PViND 1 | Set of BoolT.2.0 | (BDC2 and BDC1) |
| 601 PViND 2 | UInteger.12.4 | (PDV1) |
| 602 PViND 3 | Integer.8.16 | (PDV2) |
| 603 PViND 4 | UInteger.8.24 | (Manufacturer/vendor specific) |

604 **A.3.10 Process data description**

605 Each and every profile Device provides an input Process Data description (PDInputDescriptor)
606 indicating the composition (mapping) of the BinaryDataChannels (BDC) and ProcessDataVari-
607 ables (PDV) in the "PDinput data stream" with the necessary number of octets and/or an ade-
608 quate output Process Data description (PD Output Descriptor). The coding of the corresponding
609 parameters is defined in B.5.

610 The content of the process variable descriptors PVinD or PVoutD shall be available

- 611 • in the user manual of the profile Device,
- 612 • within the profile Device in the corresponding Index.

613 Each and every PDV or BDC respectively is described unambiguously via its descriptor PVinD
614 and/or PVoutD. Subsequent Boolean variables can be described within one descriptor. The
615 following information shall be provided within a PVinD or PVoutD respectively:

- 616 • the data type (DataType) of the particular process variable. "Set of BoolT" describes here
617 combined BinaryDataChannels (BDCs)
- 618 • the length of the data type (TypeLength) in bit, for example 6 for UInteger6
- 619 • the bit offset (Bit offset) as the beginning of the variable in the data stream
- 620 • any manufacturer/vendor specific data structures, which cannot be described via the stand-
621 ard BDC or PDV descriptors, are described via a process variable descriptor (e.g. additional
622 output data)

623 The user program within a controller (e.g. PLC) can thus read this information.

624 **A.4 Diagnosis [0x8003]**

625 The FunctionClass 0x8003 defines some optional parameters as mandatory for profile Devices.
626 These are

- 627 • Device Status
- 628 • Detailed Device Status

629 Both parameters are unchanged to the definition in clause B.2.18 and B.2.19 in [1].

630 This standardized FunctionClass [0x8003] is highly recommended for all Device profiles.

631 **A.5 Extended Identification [0x8100]**

632 The FunctionClass 0x8100 defines extended identification which can be used e.g. for localisa-
633 tion in a plant, machine, etc in any readable location format. Another parameter can contain a
634 detailed description of the specific Device like "Hot water valve", etc. Both parameter provide
635 only a sequence of characters without any interpretation within the Device itself.

636 The parameter

- 637 • Function Tag
- 638 • Location Tag

639 defined in B.6 provide the necessary non-volatile memory space.

640

Annex B (normative)

Profile relevant Device parameters

B.1 Overview

The manufacturer can provide Subindex access to objects with RecordItems, the Common Profile specification does not define this behaviour. Any overall usable software shall always use the Subindex 0 access instead as this access is granted by any Device.

The persistence or volatility of the objects is stated for each object.

The SystemCommand "Restore factory settings" (0x82) will reset all Device parameters to their default value.

The profile relevant Device parameters are specified in [1]. An overview is shown in Table B.1.

Table B.1 – General profile relevant Device parameters

Index (dec)	Object name	Access	Length	Data type	M/O/C	Remark
...						
0x0002 (2)	SystemCommand	W	1 octet	UIntegerT	M	See B.2
0x000D (13)	Profile Characteristic	R	variable	ArrayT of UIntegerT16	M	See B.4 See clause B.2.5 in [1]
0x000E (14)	PDInput Descriptor	R	variable	ArrayT of OctetStringT3	M	See B.5 See clause B.2.6 in [1]
0x000F (15)	PDOutput Descriptor	R	variable	ArrayT of OctetStringT3	M	See B.5 See clause B.2.7 in [1]
...						
0x0010 (16)	Vendor Name	R	max. 64 octets	StringT	M	See clause B.2.8 in [1]
...						
0x0012 (18)	Product Name	R	max. 64 octets	StringT	M	See clause B.2.10 in [1]
0x0013 (19)	Product ID	R	max. 64 octets	StringT	M	See clause B.2.11 in [1]
...						
0x0015 (21)	Serial Number	R	max. 16 octets	StringT	M	See clause B.2.12 in [1]
0x0016 (22)	Hardware Revision	R	max. 64 octets	StringT	M	See clause B.2.14 in [1]
0x0017 (23)	Firmware Revision	R	max. 64 octets	StringT	M	See clause B.2.15 in [1]
0x0018 (24)	Application Specific Tag	R/W	32	StringT	M	See B.2 See clause B.2.16 in [1]
0x0019 (25)	Function Tag	R/W	32	StringT	M	See B.6
0x001A (26)	Location Tag	R/W	32	StringT	M	See B.6
...						
0x0024 (36)	Device Status	R	1 octet	UIntegerT	M	See B.7 See clause B.2.18 in [1], default value is "0".

Index (dec)	Object name	Access	Length	Data type	M/O/C	Remark
0x0025 (37)	Detailed Device Status	R	variable	ArrayT of Oc- tetStringT3	M	See B.7 See clause B.2.19 in [1], default values are "0". Contains a minimum of one Event entry.
Keys M = mandatory; O = optional; C = conditional						

654

655 B.2 Mandatory SystemCommands

656 This clause describes the SystemCommands which are already defined in [1]. The Common
657 Profile Specification defines the commands defined in Table B.2 as mandatory for all profile
658 Devices.

659

Table B.2 – Parameter “SystemCommand”

Command (hex)	Command (dec)	Command name	M/O	Definition
0x01	1	ParamUploadStart	M	See clause B.2.2 in [1]
0x02	2	ParamUploadEnd	M	
0x03	3	ParamDownloadStart	M	
0x04	4	ParamDownloadEnd	M	
0x05	5	ParamDownloadStore	M	
0x06	6	ParamBreak	M	
0x82	130	Restore factory settings	M	
Key M = mandatory				

660

661 B.3 Identification parameters

662 The structure and coding is defined in clauses B.2.11, B.2.15 and B.2.16 in [1].

663 As a difference the parameter Application Specific Tag is defined with the maximum size of 32
664 octets as defined in Table B.3. The parameter shall be saved remanent and handled by the
665 DataStorage mechanism.

666

Table B.3 – Definitions for identification data objects

Index (dec)	Subindex	Offset	Access	Object name	Length (octets)	Data Type
0x0018 (24)	n/a	n/a	R/W	Application Specific Tag	32	StringT
Keys R = read W = write n/a = not applicable						

667

668 B.4 ProfileCharacteristics parameter

669 This clause describes the parameter which contains the ProfileIdentifier of the supported Device
670 profiles and FunctionClasses.

671 Table B.4 defines the structure of the parameter ProfileCharacteristics.

672

Table B.4 – Parameter “ProfileCharacteristics”

Index (dec)	Subindex (dec)	Offset	Access	Parameter Name	Length	Data type
0x000D (14)	1	$(n-1) * 2$	R	ProfileIdentifier 1	16 bit	UIntegerT16
	...					
	n	0	R	ProfileIdentifier n		
Key n = number of supported ProfileIdentifier						

673 See 5.4 for further rules regarding the ProfileIdentifier. There is no Subindex support required.

674 B.5 Process data structure descriptors

675 This clause describes the parameters which contain the structure information of the process
 676 data input and output. Each part of the process data is described with an PVinD or PVoutD.
 677 The generic rules for defining the structures are described in A.3, specific process data struc-
 678 ture definitions for ProfileIDs are defined in the corresponding profile specification like [7].

679 B.5.1 Coding of PVinD and PVoutD

680 Table B.5 shows the coding of each process variable to be placed in the descriptors using
 681 PVinD or PVoutD.

682

Table B.5 – Coding of PVinD or PVoutD

Bit	Item	Coding
Octet 1	DataType	0: OctetStringT 1: Set of BoolT 2: UIntegerT 3: IntegerT 4: Float32T 5 to 255: reserved
Octet 2	TypeLength	0 to 255 Bit
Octet 3	Bit offset	0 to 255 Bit

683

684 NOTE The abstract notation of for example a PVinD is: DataType.TypeLength.Bit_offset

685 B.5.2 PD Input Descriptor

686 Profile Devices with process input data shall use the standard Device parameter "PD Input De-
 687 scriptor" in Index 0x000E to provide the description information according to Table B.5.

688 Table B.6 defines the structure of the PD Input Descriptor regarding the offset and Subindex
 689 layout. Subindex support is not required.

690

Table B.6 – Structure of "PD Input Descriptor"

Index (dec)	Subindex (dec)	Offset	Access	Parameter Name	Length	Data type
0x000E (15)	1	$(n-1) * 3$	R	PVinD 1	24 bit	OctetStringT3
	...					
	n	0	R	PVinD n	24 bit	OctetStringT3
Key n = number of provided descriptors						

691

692 B.5.3 PD Output Descriptor

693 Profile Devices with process data output shall use the standard Device parameter "PD Out-
 694 put Descriptor" in Index 0x000F to provide the description information according to Table B.5.

695 Table B.7 defines the structure of the PD Output Descriptor regarding the offset and Subindex
696 layout. Subindex support is not required.

697 **Table B.7 – Structure of "PD Output Descriptor"**

Index (dec)	Subindex (dec)	Offset	Access	Parameter Name	Length	Data type
0x000F (16)	1	$(n-1) * 3$	R	PVoutD 1	24 bit	OctetStringT3
		
	n	0	R	PVoutD n	24 bit	OctetStringT3
Key n = number of provided descriptors						

698

699 B.6 Extended Identification parameters

700 This clause defines the extended identification parameters which can be used for overall local-
701 isation and identification of any Device.

702 The content is not predefined, the customer can write any visible string conform to his own
703 naming rules. The R/W parameters "Function Tag" and "Location Tag" shall be saved remanent
704 and handled by the DataStorage mechanism. As default it is recommended to fill the parameter
705 "Function Tag" and "Location Tag" with "****".

706 Table B.8 defines the structure of the parameters.

707 **Table B.8 – Parameter Extended Identification**

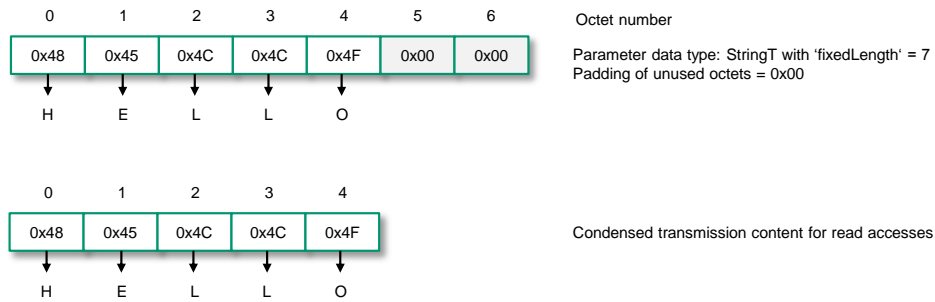
Index (dec)	Subindex (dec)	Offset	Access	Parameter Name	Length	Data type
0x0015 (21)	n/a	n/a	R	Serial Number	Max 16 octets	StringT
0x0016 (22)	n/a	n/a	R	Hardware Revision	Max 64 octets	StringT
0x0019 (25)	n/a	n/a	R/W	Function Tag	32 octets	StringT32
0x001A (26)	n/a	n/a	R/W	Location Tag	32 octets	StringT32
Key n/a = not applicable						

708

709 Opposite to the definition in clause E.2.6 in [1], the content of the parameters Function Tag and
710 Location Tag shall never be transmitted in the unmodified version with padding octets, it shall
711 always be transmitted in the condensed form. This restriction allows to use this parameters
712 even in systems with shorter string length than defined here.

713

714 Figure B.1 shows an example of this restriction.
715



716

717

Figure B.1 – Condensed transmission of StringT variables

718

719 B.7 Diagnosis parameters

720 The structure and coding is defined in clauses B.2.18 and B.2.19 in [1].

721 Table B.9 defines the structure of the Detailed Device Status regarding the offset and Subindex
722 layout. Subindex support is not required.

723

Table B.9 – Structure of "Detailed Device Status"

Index (dec)	Subindex (dec)	Offset	Access	Parameter Name	Length	Data type
0x0025 (37)	1	$(n-1) * 3$	R	Event 1	24 bit	OctetStringT3
	n	0	R	Event n	24 bit	OctetStringT3
Key		n = number of provided Event entries				

724

Annex C
(normative)

Function block definitions

C.1 Overview

This annex contains the proxy Function Blocks supporting the CommonApplicationProfileID.

The specification is based on IEC 61131-3 definitions.

As there are still some differences between the existing systems regarding the PLC system or fieldbus, the system dependent features are marked and have to be defined for each system separately.

The proxy Function Block is asynchronous, which means that the Function Block is triggered and after accomplishing the functionality the results are available.

C.2 Proxy function block (FB) for identification and diagnosis

The layout of the proxy function block for the CommonApplicationProfile Identification and Diagnosis (0x4000) which supports the FunctionClasses DeviceIdentification (0x8000), Device-Diagnosis (0x8003), and ExtendedIdentification (0x8100) is shown in Figure C.1.

The input and output data types of the proxy function block correspond to those of IEC 61131-3 (PLC programming languages).

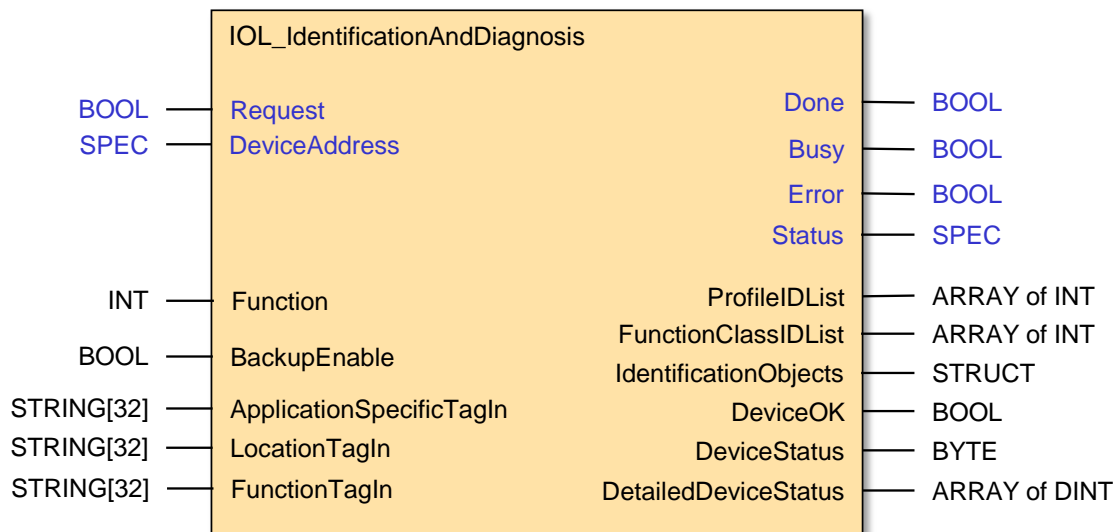


Figure C.1 – Proxy FB for Device Identification and Diagnosis

Table C.1 defines the variables of this proxy FB.

Table C.1 – Variables of "IOL_IdentificationAndDiagnosis" FB

Variable	PLC Type	Description
Inputs		
Request ^a	BOOL	A trigger causes the function selected with variable Function to be executed
DeviceAddress ^a	SPEC ^b	This variable depends on the individual fieldbus address mechanism of an SDCI Device at an SDCI Master port (see SDCI integration specification of a particular fieldbus)

Variable	PLC Type	Description
Function	INT	This variable selects the functionality to be triggered by a Request 0 = no_func A Request is neglected, no function is executed 1 = rd_all A Request starts the read back of current identification and diagnostic parameter values from the Device. 2 = rd_diag A Request starts the read back of current diagnostic parameter values by reading DeviceStatus and DetailedDeviceStatus from the Device. 3 = wr_ident A Request causes a previously applied value for ApplicationSpecificTagIn, LocationTagIn, and FunctionTagIn to be written to the Device
BackupEnable	BOOL	This variable configures the behavior of the FB in case of the requested function wr_ident. "true" = enabled The backup mechanism is triggered by the FB. "false" = disabled The backup mechanism is not triggered by the FB
ApplicationSpecificTagIn	STRING[32]	See Device parameter in clause B.2.16 in [1]
LocationTagIn	STRING[32]	See B.6
FunctionTagIn	STRING[32]	See B.6
Outputs		
Done ^a	BOOL	The signal is set, if the FB has completed a requested operation.
Busy ^a	BOOL	The signal is set, if the FB is executing a requested operation
Error ^a	BOOL	The signal is set, if an error occurred during execution of a requested operation.
Status ^a	SPEC ^b	The value represents the current status of the FB operation and executed functions. The content is system specific and contains the status information
ProfileIDList	ARRAY of INT	List of ProfileIDs supported by the Device
FunctionClassIDList	ARRAY of INT	List of FunctionClassIDs supported by the Device
IdentificationObjects	STRUCT	Structured list of identification objects, see Table C.2 for further details
DeviceOK	BOOLEAN	The signal is set when no further diagnosis info is available, it is false when further information is available at DeviceStatus and DetailedDeviceStatus
DeviceStatus	BYTE	See Device parameter in clause B.2.18 in [1]
DetailedDeviceStatus	ARRAY of DWORD	This parameter contains the type casted values from the Device parameter defined in clause B.2.19 in [1]
Key a: This variable name may be adapted to the PLC specific naming guide lines b: SPEC represents the applicable data type for this specific parameter, this may vary over different PLC systems		

747

748 The lists ProfileIDList, FunctionClassIDList, and DetailedDeviceStatus are set to 0 by default
749 and overwritten by data read from the Device.

750 The structured information in the variable IdentificationObjects is specified in Table C.2.

751 The default value is provided when the corresponding parameter is not already read from the
752 Device or not available in the Device.

753

Table C.2 – Elements of the IdentificationObjects

Name	PLC Type	Default	Remark
VendorID	WORD	00 00	See clause B.1.8 in [1]
DeviceID	DWORD	00 00 00 00	See clause B.1.9 in [1]
VendorName	STRING[64]	“na”	See clause B.2.8 in [1]
VendorText	STRING[64]	“na”	See clause B.2.9 in [1]
ProductName	STRING[64]	“na”	See clause B.2.10 in [1]
ProductID	STRING[64]	“na”	See clause B.2.11 in [1]
ProductText	STRING[64]	“na”	See clause B.2.12 in [1]
SerialNumber	STRING[16]	“na”	See clause B.2.13 in [1]
HardwareRevision	STRING[64]	“na”	See clause B.2.14 in [1]
FirmwareRevision	STRING[64]	“na”	See clause B.2.15 in [1]
ApplicationSpecificTag	STRING[32]	“na”	See clause B.2.16 in [1]
LocationTag	STRING[32]	“na”	See B.6
FunctionTag	STRING[32]	“na”	See B.6

754

Annex D (normative)

IODD definition and rules

755
756
757
758

D.1 Overview

760 The objective of the Common Profile specification is to ease the integration of Devices and to
761 provide additional information in a uniformed manner. The integration is part of the specialised
762 profile specifications, the uniformed information about profile support is part of this clause.
763 As the parameter and the behavior is specified the look and feel of the Devices should also be
764 harmonized, otherwise the appearance of the same profile is different between different manu-
765 facturer.

766 To achieve a common look and feel, the IODD content has to be defined as well. This clause
767 includes the rules for the naming conventions and menu layout.

D.2 Constraints and rules

769 The following naming conventions shall be considered for all additional profile specifications :

- 770 – Every object name shall start with an appropriate abbreviation of the FunctionClass
- 771 – The object name shall be human-readable and can be abbreviated to shorten the name
- 772 – Commands shall be named in imperative
- 773 – A menu group shall represent the FunctionClass without abbreviation
- 774 – SingleValues shall be human-readable and are abbreviated to shorten the name
- 775 – The predefined name shall always be used in any Device specific IODD
- 776 – A vendor/manufacture specific extension can be added to the predefined name in order to
777 enable vendor specific explanations even in different languages, these shall be separated
778 by “ – “
- 779 – The menu entries shall be located in the specified menu section
- 780 – The menu entries shall not be altered in layout and structure

781

D.3 Name definitions

D.3.1 Profile type characteristic names

784 The profile characteristic name defined in 7.1 and in separated profile specifications shall be
785 used whenever any profile functionality is referenced in the IODD.

D.4 IODD Menu definitions

D.4.1 Overview

788 Examples for layouts of Port and Device configuration tools are shown in clause 11.7 in [1].

789 Within these examples the IODD defines the parameter layout of the connected device. In this
790 clause the object and parameter layout of the ProfileIdentifier is specified.

791 To harmonize the layout, the parameter shall be referenced in the menu. If RecordItems are
792 available, these shall be referenced in the menu. The shown variable figures and the SingleVal-
793 ues are examples.

D.4.2 Menu structure of the ProfileIdentifier

795 In Figure D.1 the menu structure of a sample profiled Device is specified, it shall be located in
796 the identification section of the menu.

- Profile Support	
- Profile Characteristic	
DeviceProfile 1	First DeviceProfile
...	
DeviceProfile d	Last DeviceProfile
ApplicationProfile 1	First ApplicationProfile
...	
ApplicationProfile a	Last ApplicationProfile
FunctionClass 1	First additional FunctionClass
...	
FunctionClass f	Last additional FunctionClass

Note d = amount of supported device profiles
 a = amount of supported application profiles
 f = amount of supported function classes

797

798

Figure D.1 – Data flow within automation systems

799 The ProfileIDs shall be sorted in ascending order, the different types shall be distinguished by
 800 their associated Profile type name like DeviceProfile, ApplicationProfile and FunctionClass.

Annex E
(informative)
Device integration strategies into automation systems

E.1 Overview

E.1.1 Data and information providers and consumers

Ever since SDCI enables digital communication it is possible for the entire automation hierarchy to exchange data and information directly with nearly all kinds of sensors and actuators. While controllers such as PLCs or industrial PCs take over the task of automatically controlling machines and plants, operators are monitoring and maintaining the equipment and processes through human-machine-interfaces. More and more of these machines and plants are integrated in higher level enterprise data processing systems. For commissioning and trouble-shooting engineering tools are temporarily engaged. Figure E.1 shows the principle data flow between all of these systems including Masters and Devices. All of these can be provider and consumer of data and information (see 3.2.1, 3.2.3, and 3.2.6).

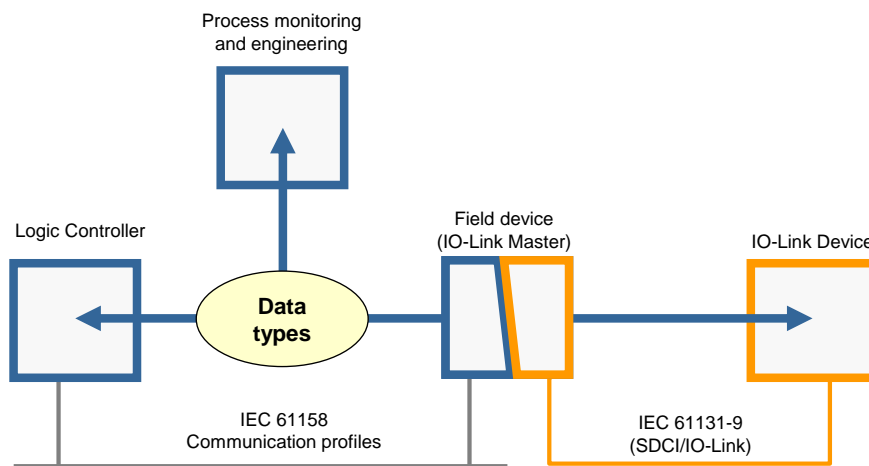
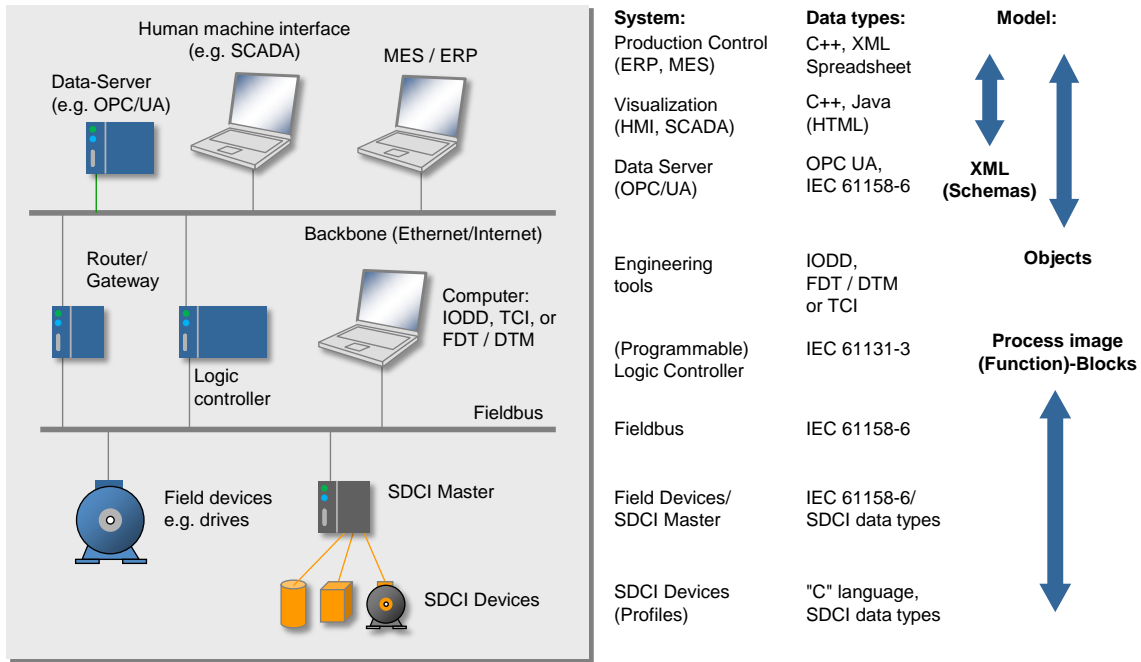


Figure E.1 – Data flow within automation systems

Unfortunately, there is no straightforward direct exchange of data and information between any of these systems since all of them are using their own data types and codings, even the communication systems (see Figure E.2).

Traditionally, the PLC has been a hub between the connected sensors and actuators and the upper level systems and acted as a "representative" for process data. However, with the advent of fieldbuses and now with SDCI direct access to identification and maintenance information is possible and a number of software tools are now eager to acquire data and information such as

- commissioning and diagnosis software,
- asset management,
- audit trailing,
- manufacturing execution systems,
- data server (OPC UA),
- process monitoring (SCADA),
- condition monitoring,
- WEB server.



834

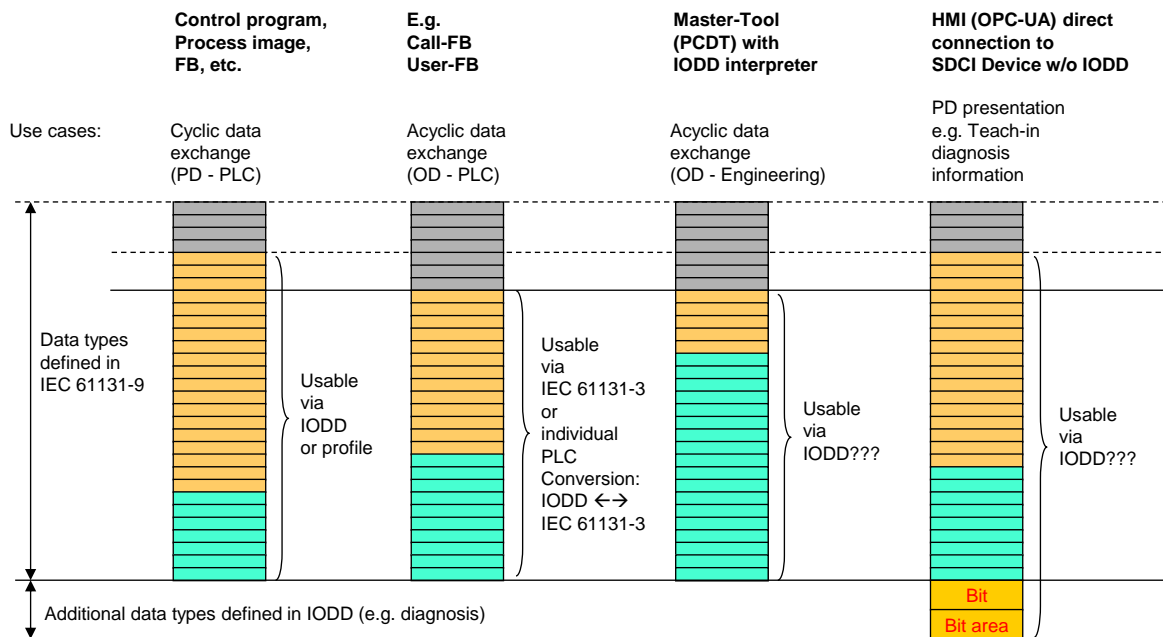
835

Figure E.2 – Data types within automation systems

836 **E.1.2 Consistency of data and information**

837 In most cases it is possible for a PLC programmer to adjust any SDCI data structures via mask-
 838 ing, bit shifting, and/or type casting in PLCs to prepare cyclic Device data ("PD") and acyclic
 839 Device data ("OD") for the processing within PLCs. However, this causes increased engineering
 840 efforts and risk of erroneous program codes.

841 Complex data structures are even worse for independent software tools, where no access to
 842 IODD information is available.



843

844

Figure E.3 – Use cases and data type recommendations

845 Direct access to Devices via SDCI may be impossible or at least associated with intricate ad-
 846 aptation steps. This document provides assistance via consistency tables and rules for the
 847 design of easy to handle data types and data structures.

848 Table E.1 shows the list of the most important PLC data types according to IEC 61131-3. These
849 data types are the initial point for the reference tables. (to be defined).

850

Table E.1 – PLC data types (IEC 61131-3)

Data type	Definition	Length (bit)	Value range
BOOL	boolean	1	TRUE, FALSE or 1,0
BYTE	octet	8	B#16#00 to B#16#FF
WORD	word	16	W#16#0000 to B#16#FFFF
DWORD	double word	32	DW#16#00000000 to ...
LWORD	long word	64	LW#16#0000000000000000 to ...
USINT	unsigned short integer	8	0 ... 255
UINT	unsigned integer	16	0 .. 65535
UDINT	unsigned double integer	32	-2147483648... 2147483647
ULINT	unsigned long integer	64	-9,2 Trio... 9,2 Trio
SINT	short integer	8	-128... 127
INT	integer	16	-32768... 32767
DINT	double integer	32	-2147483648... 2147483647
LINT	long integer	64	-9,2 Trio... 9,2 Trio
REAL	real	32	$\pm 1,18 \times 10^{-38}$ to $3,40 \times 10^{38}$
LREAL	long real	64	$\pm 2,2... \times 10^{-308}$ to $1,79... \times 10^{308}$
TIME	duration (ms)	32	
LTIME	duration (ns)	64	
DATE	date	16	
TIME_OF_DAY	time	32	
CHAR	character	8	
STRING	character sequence	> 2 x 8	
NOTE Data types marked in grey may not be available in older PLC systems.			

851

852 E.1.3 Profile specific data types

853 Any profile can define specific data types usable for the profile. It is preferred to define struc-
854 tures based on data types from Table E.1 to achieve an easy support of the parameters in the
855 PLC systems.

856 E.1.4 Memory and transmission octet order

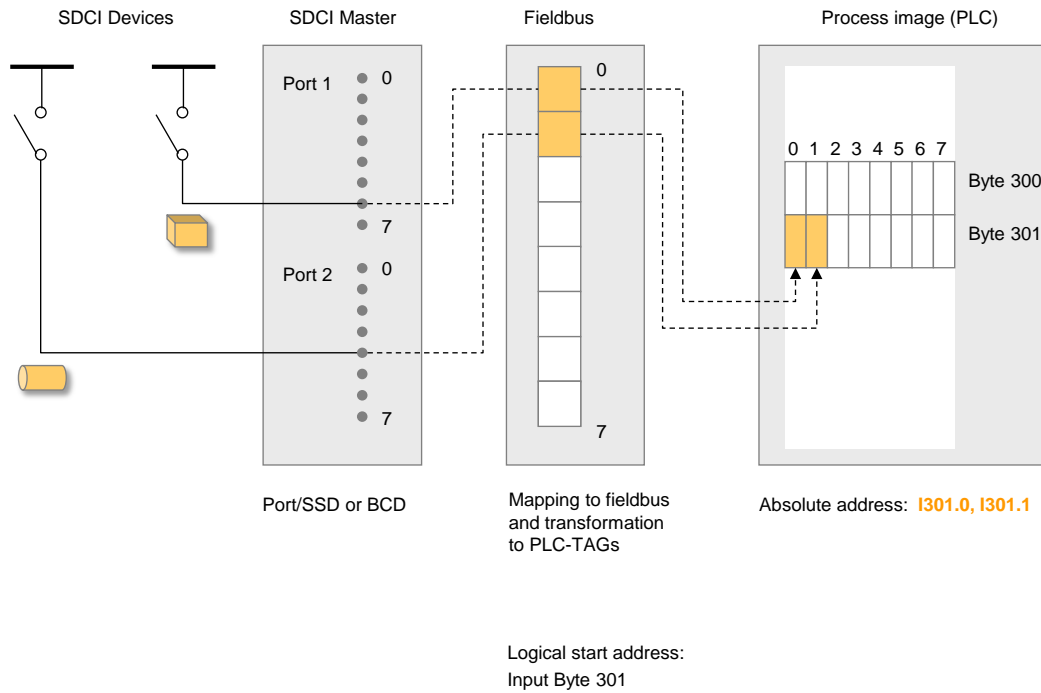
857 One critical aspect when considering the data type consistency is the memory and transmission
858 octet order as demonstrated in Figure 1.

859

860 E.2 Integration via process image

861 E.2.1 General

862 The target of the process values is the user program coded in the PLC. The data is similar to
863 the data provided by any other fieldbus device. Simple binary data is provided as boolean data.
864 The transport and placement is shown in Figure E.4.



865

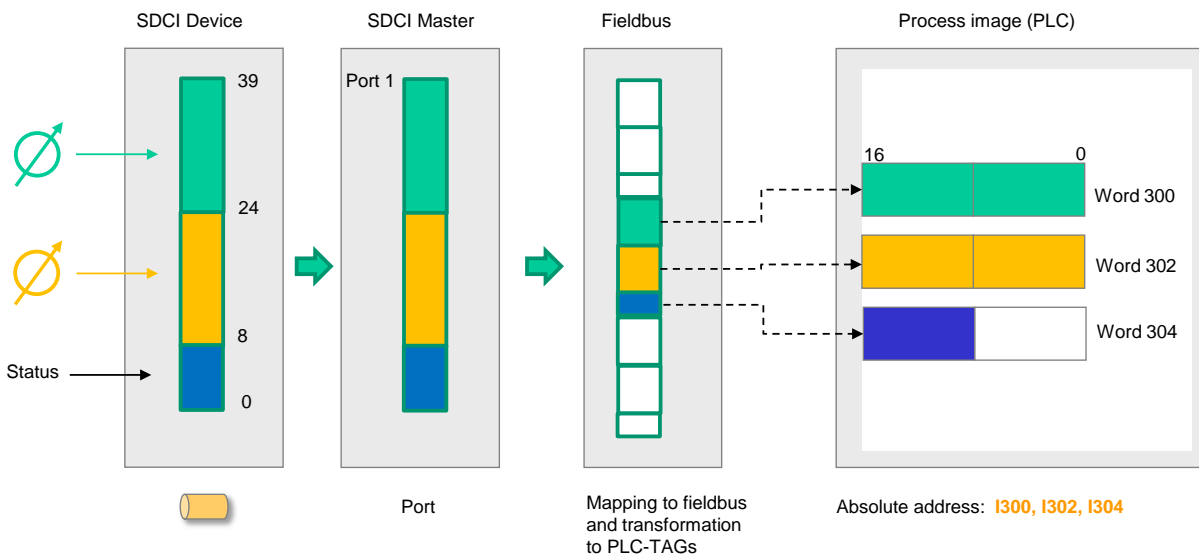
866

Figure E.4 – Transformation from SDCI to process image of boolean data

867

Measurement data is provided with data types greater one octet and the corresponding data types according to Table E.1. The transport and placement is shown in Figure E.5.

868



869

870

Figure E.5 – Transformation from SDCI to process image of complex data

871

E.2.2 Import of TAG lists based on the IODD

872

To reduce the engineering effort for the integration it is possible to generate and provide function blocks for individual Devices of Device families. Any vendor can provide the generator or the ready-to-use function block.

873

874

875

876

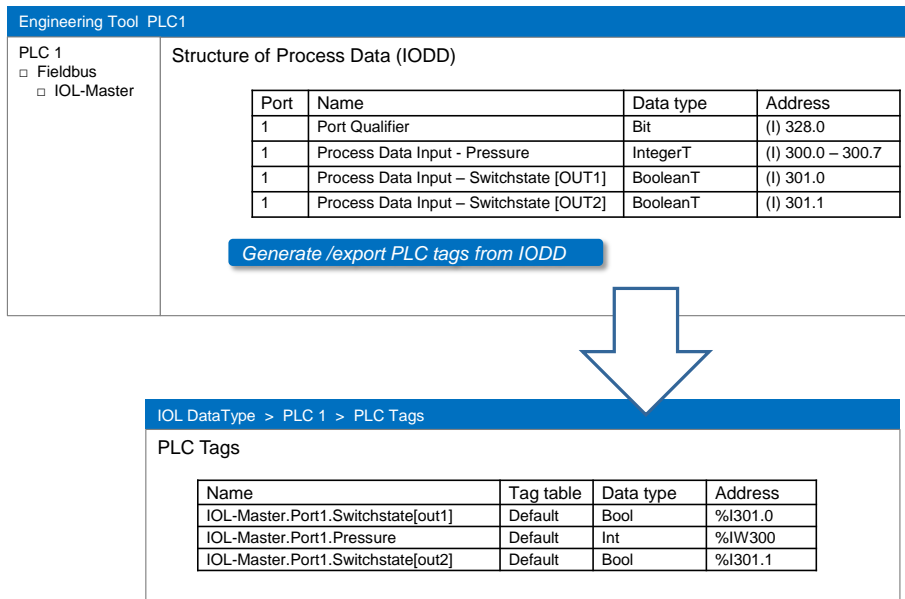
It is also possible to generate lists of tags to be used in the PLC generated on base of the IODD. This list of tags can be imported in the engineering system and allows to use the vendor defined parameter names and settings.

877

878

879

Figure E.6 shows the generation of predefined tags of process data variables.



880

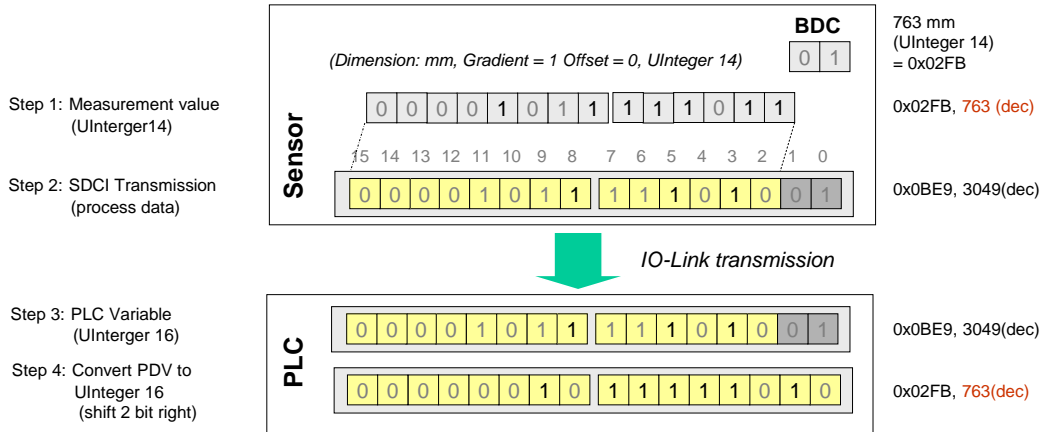
881

Figure E.6 – Integration via process image

E.2.3 Decomposing packed process data values

883 As defined in A.3.1 the process data mapping may contain packed data structures like 14 bit
 884 plus 2 bit in one 16 bit variable, like the data structure shown in Figure E.7.

885 Figure E.7 illustrates the relationship between a dimensioned PDV and its PLC variable for this
 886 packed structure.



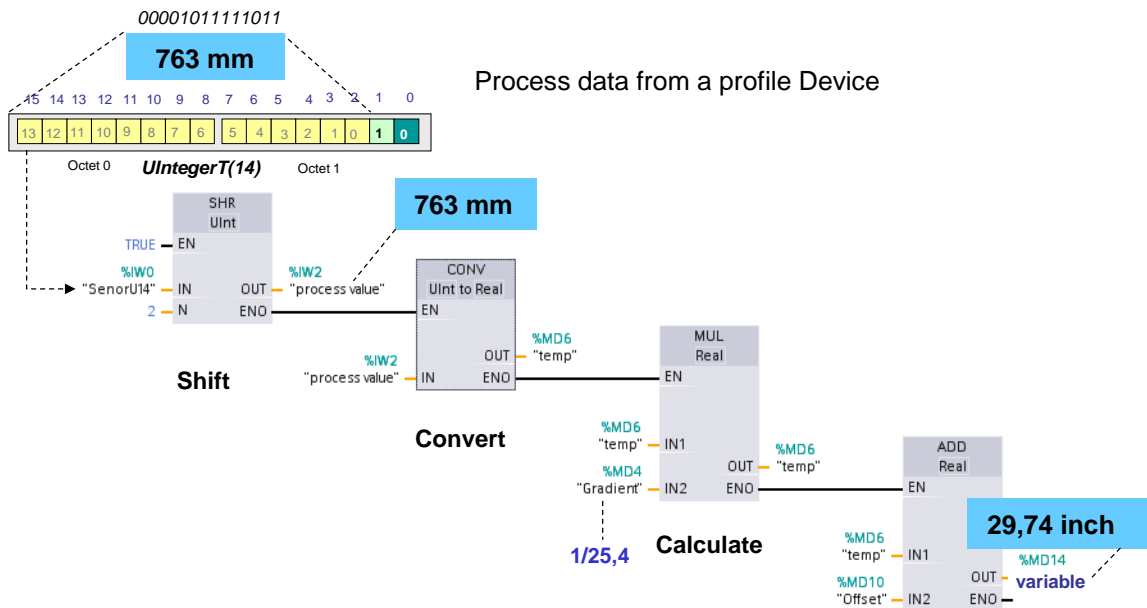
887

888

Figure E.7 – Relationship between a dimensioned PDV and its PLC variable

889

890 Figure E.8 demonstrates a typical PLC user program for a measurement value conversion. A
 891 PLC user program transforms the PDV via shift operations into a 16 bit UInteger variable.



892

893

Figure E.8 – Example PLC program for a measurement value conversion

894

895 **E.3 Integration via PROXY function block (IEC 61131-3)**

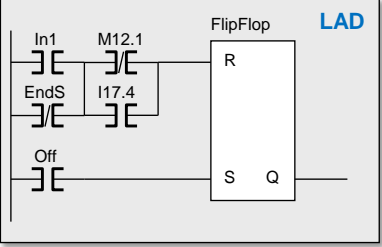
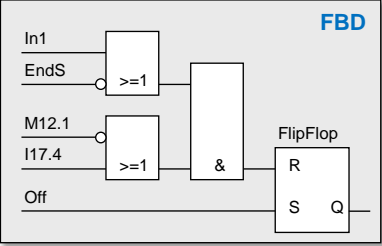
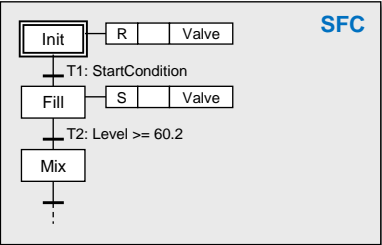
896 **E.3.1 IEC 61131-3 programming languages**

897 In contrast to the classic Information Technology (IT) with its programming languages Assem-
 898 bler, C, C#, Java, etc. the automation technology developed its own set of programming lan-
 899 guages such as IL (Instruction List), LD (Ladder Diagram), FBD (Function Block Diagram), ST
 900 (Structured Text, which is close to the PASCAL language), and SFC (Sequential Function Chart)
 901 each with its own advantages and historic background (see Table E.2). This development was
 902 triggered by the advent of programmable logic controllers (PLC) in the 70's, which started re-
 903 placing the relay based logic controls. The user was enabled to "draw" his "relay circuits" on
 904 the screen (relay ladder logic) that were translated into machine code of microprocessors and
 905 processed there in a sequential and cyclic manner (Linear Code). At the beginning of a cycle
 906 the information of input "peripherals" (sensors, switches, etc.) were read into a "process image
 907 memory" and at the end of the same cycle the result information was written into output "pe-
 908 ripherals" (relays, switches, valves, etc.). Up to now, this "polling" principle proved to be a very
 909 robust data processing procedure especially with thousands of input and output signals.

910 These programming languages are standardized in IEC 61131-3 [8]. The following table char-
 911 acterizes the idea of the basic features and graphical layouts of the languages. The process
 912 variables are either the physical address (e.g. I17.4) of an I/O-module or a unique symbol (e.g.
 913 EndS) of a signal in the field. See [9] and [10] for additional information on IEC 61131-3 pro-
 914 gramming languages.

915

Table E.2 – Characteristic of IEC 61131-3 programming languages

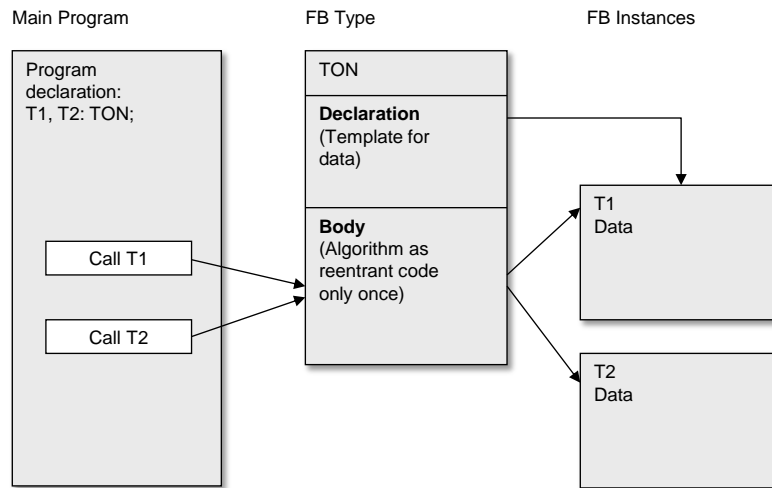
Language representation	Characteristics
 <p style="text-align: right; color: blue;">LAD</p>	<p>Ladder Diagram (LD) German: "Kontaktplan" (KOP) Derived from the former Relay Ladder Logic diagrams on "blue prints". Allows immediate fault detection through online status of the signals within the graphical representation.</p>
<pre> U(O In1 ON EndSw) U(ON M12.1 O I17.4) R FlipFlop U Off S FlipFlop </pre> <p style="text-align: right; color: blue;">IL</p>	<p>Instruction List (IL) German: "Anweisungsliste" (AWL) Derived from Assembler Language. Most flexible for experienced programmers. Portability of programs from one PLC to another is difficult due to machine code dependency.</p>
 <p style="text-align: right; color: blue;">FBD</p>	<p>Function Block Diagram (FBD) German: "Funktionsplan" (FUP) Derived from Circuit Diagrams of electronic boards. More comprehensible than LD with complex logic. However, root cause fault detection of machines needs more (mental) steps for the user.</p>
<pre> VAR MAX : INT := 10_000; MIN : INT := -5_000; END_VAR BEGIN IF IN > MAX THEN OUT := MAX; ELSEIF IN < MIN THEN OUT := MIN; ELSE OUT := IN; END_IF; </pre> <p style="text-align: right; color: blue;">ST</p>	<p>Structured Text (ST) German: "Strukturierter Text" (ST) Derived from the PASCAL programming language. Its purpose is to easily support mathematical type of tasks or complex data manipulation in automation. These program parts can be encapsulated within Function Blocks and hidden from maintenance people. Knowhow protection is possible. This language is best suited for portability of PLC programs.</p>
 <p style="text-align: right; color: blue;">SFC</p>	<p>Sequential Function Chart (SFC) German: "Ablaufkettensprache" (AS) Goes back to Harel's State Charts for finite state machines in 1967. Programming of states and transitions can be done by the other languages for program logic (IL, LD, and FBD). This language is most efficient in respect to programming effort, debugging, risks at program changes, and root cause fault detection. Highly recommended for machine programs. Acceptance limited due to missing training at schools and universities.</p>

916

917 E.3.2 Function Blocks and Function Calls according IEC 61131-3

918 While the first PLCs were providing unstructured so called "Linear Code", the next generation
919 offered technology to better structure the programs. Thus, common to all of the IEC 61131-3
920 languages is the powerful element of the "Function Block" (FB). With the help of FBs it could
921 be managed to satisfy the hardware paradigm of logic components with interfaces and encapsulated
922 functionality including memory effects and thus to support reusability (see Figure E.9).
923 On the other hand, the associated type/instance concept follows the direction of object orientation
924 within the office automation (IT) in an ideal manner:

- 925 a) A piece of consistent program that shall be reusable can be declared a Type-FB and entered
 926 in a program library. The re-entrant code of this Type-FB can have behavior (state machine)
 927 and several input and output variables.
- 928 b) Hence, in a real application program this Type-FB can be implemented as an Instance-FB
 929 with different persistent data sets (FB Instances). Local variables within those FBs can be
 930 used for (volatile) temporary functions.
- 931 c) The FB Instances can be called anytime within the Main Program.



932

933

Figure E.9 – Function block and its instance data

934 Function Calls are following a similar concept of reusable code. However, there is only one
 935 return value, no behaviour and no persistent local data. The unit conversion of a variable is an
 936 example of a Function Call (FC).

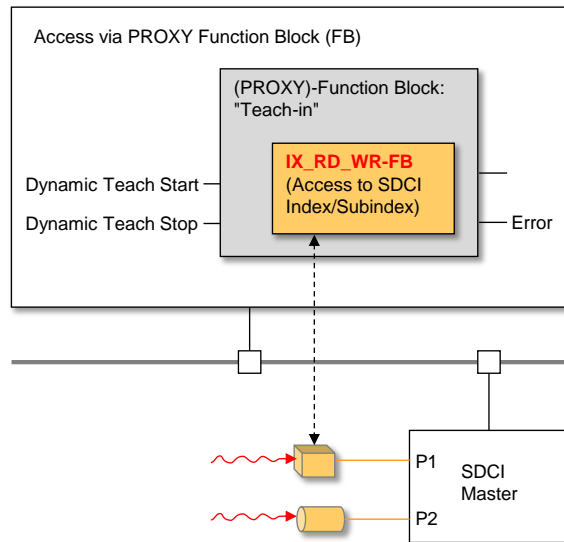
937 See [9] and [10] for additional information on Function Block and Function Call concepts.

938 E.3.3 Concept of PROXY Function Blocks

939 PROXY Function Blocks are representatives of field devices on fieldbuses or lower level SDCI
 940 Devices. These function blocks are translating the transmitted data structures (octets) into easy
 941 user understandable input and output signals and data at the PROXY-FB interface level (see
 942 Figure E.10). Usually, the PROXY-FBs are working with a standard communication function
 943 block platform (fieldbus to SDCI) to contact their Devices (see details in Figure E.11).

944 For complex Devices such as drives, RFID reader/writer, weighing and dosage systems, the
 945 PROXY FBs can become rather complex and the usage of sequential function chart pro-
 946 gramming (SFC) nearly impossible. In these cases a modular design of the PROXY-FBs using
 947 Function Calls is more appropriate. More details for such a design can be retrieved from [11].

948 Figure E.10 shows the integration of a proxy function block using the generic communication
 949 function block which is shown more detailed in Figure E.11

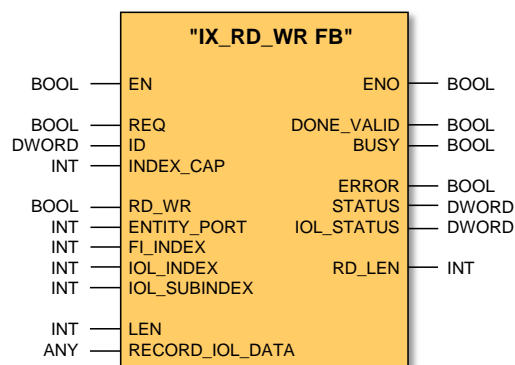


950

951

Figure E.10 – PROXY FB using standardized SDCI communication FB

952



953

954

Figure E.11 – Standardized SDCI communication FB "IX_RD_WR"

955 The responsibility for the standardized communication FB is on behalf of the system manufac-
956 turer (PLC and/or engineering tool).

957 The responsibility for the PROXY-FB is on behalf of a profile group for profile Devices or a
958 manufacturer/vendor for specific Devices.

959

960

961 **E.3.4 Device profile activities**

962 It is the responsibility of the Device profiles to specify a proxy function block for each Common-
963 ApplicationProfile or DeviceProfile if this supports the engineering of profile Devices.

964 The specification shall contain

- 965 • parameter specifications
- 966 • state machines for dynamic behavior
- 967 • optionally pseudo code close to ST (Structured Text programming language)

968 to provide the same functionality in most of the PLC systems.

969

970

971 E.4 Integration into self-configuring systems

972 It is possible to compose self-configuring systems based on the ProfileIdentifier and the corre-
973 sponding parameters or behaviour which read out the Device abilities. Then these systems may
974 generate appropriate FunctionBlocks or system components to provide standardized function-
975 ality based on the detected Devices.

976 Precondition for this feature is the availability of Devices conform to distinct profiles.

977

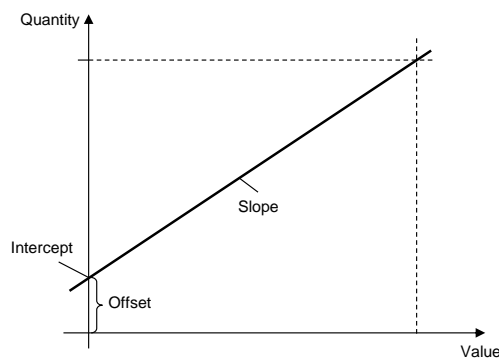
978
979
980

Annex F (informative) Scaling and dimensions

981 F.1 Gradient and offset

982 Normally, the ProcessDataVariable (PDV) of a profile Device carries a measurement value of a
983 physical or chemical quantity within the data structures (PDV) defined by the manufacturer/ven-
984 dor of the Device. See clause A.3.2 for details.

985 The transmitted value can be converted into a dimensioned value (°F, °C, inch, m, etc.) via a
986 linear equation $y = m \cdot x + b$. "m" represents the slope and "b" the intercept with the y coordinate.
987 Within these profile definitions, "Slope" is called "Gradient" and the value of the intercept is
988 called "Offset". Figure F.1 illustrates the relationships.



989

990 **Figure F.1 – Value to quantity conversion via linear equation**

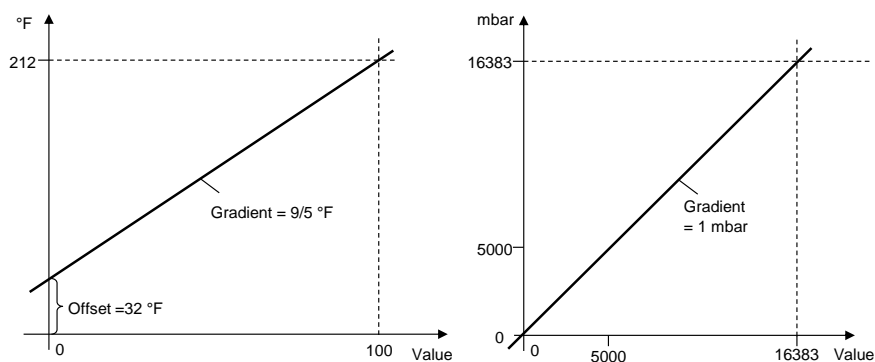
991 The manufacturer/vendor is responsible for the provision of the "Gradient" and the "Offset"
992 values for the conversion equation (1).

$$\text{Variable} = \text{Gradient} \times \text{PDV} + \text{Offset} \quad (1)$$

993

994 F.2 Conversions

995 Usually the data type for Gradient and Offset is Float32T (Überarbeiten!). With the help of this
996 information any computer software or PLC can calculate the dimensioned variable out of the
997 transmitted PDV. Figure F.2 illustrates two conversion examples for pressure and temperature.



998

999

Figure F.2 – Conversion examples

1000 Usually, the transmitted PDV value is based on a dimensioned measurement value as shown
1001 in the right example of Figure F.2 (pressure in mbar). In the left example a dimensioned tem-
1002 perature measurement value (°C) is converted in °F.

1003
1004
1005

Annex G (normative) **Profile testing and conformity**

1006 **G.1 General**

1007 **G.1.1 Overview**

1008 It is the responsibility of the vendor/maker of a profile Device to perform a conformity
1009 testing according to the test specification [6] and to provide a document similar to the manufac-
1010 turer declaration defined in [1] or based on the template downloadable from the IO-Link website
1011 (www.io-link.com).

1012 **G.1.2 Issues for additional testing/checking of profile Devices**

- 1013 • Identification complete and correct?
- 1014 • Descriptors available and correct?
- 1015 • All rules observed?
- 1016 • Switching behavior conform to the specification?
- 1017 • FunctionClasses available and correct?
 - 1018 - Indices available and correct?
 - 1019 - Read/write correct?
 - 1020 - Data structures: Record? Value ranges?
 - 1021 - Behavior of the FunctionClass conforms to the specification?
- 1022 • Extract BDCs (switching functions) from user manual or IODD and check conformity with
1023 the specification
- 1024 • Checklist: checkbox "relevant" and checkbox "verified"
- 1025 • IODD: see [3]

1026
1027

1028
1029
1030

Annex H
(informative)
Information on conformity testing of profile Devices

1031 Information about testing profile Devices for conformity can be obtained from the following or-
1032 ganization:

1033 **IO-Link Community**
1034 Haid-und-Neu-Str. 7
1035 76131 Karlsruhe
1036 Germany
1037 Phone: +49 (0) 721 / 96 58 590
1038 Fax: +49 (0) 721 / 96 58 589
1039 E-mail: info@io-link.com
1040 Web site: <http://www.io-link.com>
1041

1042

1043

Bibliography

- 1044 [1] IO-Link Community, *IO-Link Interface and System*, V1.1.2, July 2013, Order No.
1045 10.002
- 1046 [2] IEC 61131-9, *Programmable controllers – Part 9: Single-drop digital communication*
1047 *interface for small sensors and actuators (SDCI)*
- 1048 [3] IO-Link Community, *IO Device Description (IODD)*, V1.1, July 2011, Order No. 10.012
- 1049 [4] IEC/TR 62390:2005, *Common automation device profile guideline*
- 1050 [5] IEC 60050 (all parts), *International Electrotechnical Vocabulary*
- 1051 [6] IO-Link Community, *IO-Link Test Specification*, V1.1.2, July 2014, Order No. 10.032
- 1052 [7] IO-Link Community, *IO-Link Smart Sensor Profile Ed.2*, V1.0, March 2017, Order No.
1053 10.042
- 1054 [8] IEC 61131-3:2013, *Programmable controllers - Part 3: Programming languages*
- 1055 [9] Frank Petruzella, *Programmable Logic Controllers*, 4th edition, McGraw-Hill, 2010,
1056 ISBN-13: 978-0073510880
- 1057 [10] Karl-Heinz John, Michael Tiegelkamp, *Programming Industrial Automation Systems –*
1058 *Concepts and Programming Languages, Requirements for Programming Systems, De-*
1059 *cision-Making Aids*, 2nd edition, Springer, 2010, ISBN-13: 978-3642120145
- 1060 [11] PLCopen: <www.plcopen.org>
- 1061 [12] ISO/IEC 19505-2:2012, Information technology – Object Management Group Unified
1062 Modeling Language (OMG UML) – Part 2: Superstructure

1063

1064

© Copyright by:

IO-Link Community
Haid-und-Neu-Str. 7
76131 Karlsruhe
Germany

Phone: +49 (0) 721 / 96 58 590

Fax: +49 (0) 721 / 96 58 589

e-mail: info@io-link.com

<http://www.io-link.com/>



IO-Link